PLM Industry Summary

Editor: CIMdata News Team
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CIMdata News

Aerospace & Defense PLM Action Group to Sponsor a Webinar on The Code of PLM Openness

23 September 2025

Members of the Aerospace & Defense PLM Action Group (AD PAG) will sponsor a webinar on advancing the Code of PLM Openness (CPO). The webinar, The Code of PLM Openness – what it is and why it matters now more than ever!, will take place at 11:00 a.m. EDT on Tuesday, 21 October 2025.

Product Lifecycle Management (PLM) has become indispensable in the digital age, enabling organizations to coordinate every stage of a product's journey from conception to end-of-life. In today's fast-evolving supply chains, open systems architecture and adherence to the Code of PLM Openness are critical.

Initially developed in 2012 by the prostep ivip Association, the CPO was a response to the industry embracing the service-oriented approach to technology and computing for access to engineering data. Since then, the concept has evolved into a holistic approach to open systems architecture, accompanied by a corresponding standard that includes a self-assessment and organizational certification. In May 2025, CIMdata, acting on behalf of the AD PAG, and the prostep ivip Association established a Memorandum of Understanding in which their member companies will cooperate to support the further development and adoption of the CPO.

This webinar will reflect on the core concepts of PLM and explore the transformative value of open systems in supply chain contexts with a foundation anchored in the use of the CPO.

Attendees will:

- Understand the core concepts of PLM and Open Systems
- Learn about the different product representations used in a supply chain context
- Grasp the basic constructs of the CPO
- Gain insight into using the CPO Self-Assessment as a tool
- Find out how they can actively participate in and contribute to the evolution of the CPO

According to Kenny Swope, Senior Manager of PLM Technical Excellence at Boeing, a Founding Member of the AD PAG, "The fundamental purpose of a product lifecycle management (PLM) system is to enable the business to effectively and efficiently manage one of its most valuable assets, its data. To that end, PLM is positioned perfectly at the intersection of the product, the means of production, the supplier, and the customer to provide data of the highest quality and integrity all day, every day. Using technology coupled with business processes that leverage standards-based, open architectures, which can be assembled through federated value streams, is a win–win for the OEM, the supplier, the customer, and the market. Using tools like the Code of PLM Openness (CPO) gives the A&D industry a powerful measurement that can be

used to objectively assess the significance of integration when supply chains are formed and managed."

This webinar is ideal for anyone involved in product program integration, systems engineering, PLM program planning, and PLM systems architecture. It is especially relevant for those involved in product, production, or service digitalization and digital transformation. Specific roles that would benefit from attending include product program managers, supply chain managers, systems engineers, PLM solution architects, and business analysts.

To find out more, visit https://www.cimdata.com/en/education/educational-webinars/webinar-the-code-of-plm-openness-what-it-is-and-why-it-matters-now-more-than-ever. To register, please visit https://register.gotowebinar.com/register/6842252512421396574.

Acquisitions

Accenture Announces Intent to Acquire Orlade Group to Expand Capital Projects Capabilities for Energy, Utilities, Rail, Aerospace and Defense Clients

22 September 2025

Accenture has announced its intent to acquire French Orlade Group ("Orlade"), which provides advisory and project management services for capital projects through its subsidiaries, which include Op^2 and pmO. The acquisition would significantly expand Accenture's capabilities to help clients optimize their investments in large-scale, long-term projects, such as nuclear power plants, power grids, rolling stock, defense systems and space launch systems.

Op^2's services include advising clients on how they can organize and execute capital projects more successfully with lead time reduction expertise, key best practices for large-scale project management and predictive data-driven models. pmO's project management processes and tools help clients deliver capital projects on time and on budget.

Orlade and its subsidiaries would bring approx. 200 professionals, most of which are based in Paris and Bordeaux. The company's international locations include Montréal (Canada) and Brisbane (Australia). Their teams would join Accenture's infrastructure and capital projects practice within Industry X.

Accenture's planned acquisition would come at a time in which organizations developing capital projects are facing many challenges, ranging from increased scrutiny from stakeholders to supply chain issues to staffing shortages to cybersecurity risks. As a result, only 6% of organizations surveyed deliver projects on or ahead of schedule. Two-thirds miss their targets, adding an average of 29% in labor costs and penalty fees to the bill, research from Accenture shows.

Koen Deryckere, Accenture France & Benelux market unit lead, said: "This acquisition would strengthen our position in France and boost our ability to help clients reinvent how they plan and execute large-scale projects in the energy, utilities, rail, aerospace and defense sectors. It

would enhance our capital project management expertise, from advisory to execution, and leverage advanced technologies like generative AI to drive large-scale, responsible transformation."

Flavien Parrel, who leads Accenture Industry X for France and Benelux, added: "Orlade is an experienced leader in helping organizations successfully plan and execute complex industry projects. Their team's expertise would complement our leadership in digital and technology, where generative AI offers immediate productivity gains to our capital projects clients in areas such as data compilation, analysis, and the production of technical deliverables."

Orlade was founded in 2005 by Pascal Oriot, Sylvain de Robert and Frederic Laforce. In a joint statement, they pointed out that Orlade's expertise in the full lifecycle of capital projects in industrial sectors, combined with Accenture's leadership in digital and AI, would create a unique capability to deliver future standout projects for clients. Together, both companies could help clients navigate complexity with clarity, bold thinking and a clear focus on delivery.

Accenture has been scaling its capabilities for helping clients with their infrastructure and capital projects in Europe and North America continuously over the past two years. Earlier in 2025, it acquired construction consultancy Soben in Scotland and engineering managed services company IQT Group in Italy. In 2024, it bought BOSLAN, a management services provider for net-zero infrastructure in Spain. In 2023, US advisory and management company Anser Advisory and Canadian consulting and program management company Comtech became part of Accenture.

Terms of the transaction were not disclosed. Completion of the acquisition is subject to customary closing conditions.

PROS Holdings, Inc. Enters Into Definitive Agreement to Be Acquired by Thoma Bravo

22 September 2025

PROS Holdings, Inc. ("PROS"), a leading provider of AI-powered SaaS pricing and selling solutions, and Thoma Bravo, a leading software investment firm, announced that they have entered into a definitive agreement under which PROS will be acquired by Thoma Bravo in an all-cash transaction valuing PROS at approximately $1.4 billion.

Under the terms of the agreement, PROS shareholders will receive $23.25 per share in cash, representing a premium of approximately 41.7 percent over PROS' closing share price on September 19, 2025, the last full trading day prior to the transaction announcement, and a 53.2 percent premium to PROS' volume weighted average share price over the 30-day period ending the same date. Upon completion of the transaction, PROS will become a private company with the benefit of Thoma Bravo's operating capabilities, capital support and deep sector expertise, and will be well positioned to continue delivering on key strategic priorities, including advancing AI innovation and agentic intelligence, expanding market reach and optimizing go-to-market execution.

“This transaction is the culmination of a strategic review process undertaken by the PROS Board of Directors that included discussion with a number of parties,” said Bill Russell, Non-Executive Chairman of the PROS Board of Directors. “We are pleased to reach this agreement with Thoma Bravo, which delivers significant and immediate cash value to our shareholders and we believe is the best path forward for PROS and all of our stakeholders.”

“Today marks an exciting milestone for PROS,” said Jeff Cotten, President and CEO, PROS. “Thanks to the deep expertise and decades of innovation delivered by our team, PROS has become a complete and intelligent commercial platform to help businesses win. With Thoma Bravo, I am confident that we will be able to achieve our operational and market ambitions for the benefit of our customers. As a private company, PROS will be more agile and have greater flexibility to invest in innovation and expand our platform, building on our leadership position and enabling us to remain at the forefront of AI-powered enterprise transformation.”

“We are thrilled to back Jeff and the talented PROS team as they continue to build on their leadership position to further advance AI innovation," said A.J. Rohde, a Senior Partner at Thoma Bravo. “In today’s volatile market environment, customers are increasingly looking to PROS’ AI-powered pricing and selling solutions to provide them with real-time, data-driven decision making that enables them to precisely capture demand at competitive price points through customized prices and offers. We are confident we can apply our operational expertise and our deep experience working with market-leading companies to accelerate PROS’ growth."

“Jeff and his team have created a platform that companies across industries trust to help them compete and win,” said Matt LoSardo, a Principal at Thoma Bravo and Ryan Scheffler, a Vice President at Thoma Bravo. “We have been long impressed by PROS’ track record of innovation and the tangible results they deliver for customers. We are excited to work together to continue delivering AI innovation, expand the platform’s capabilities and leverage Thoma Bravo’s resources and expertise to drive the next phase of growth.”

Transaction Details

The transaction, which has been unanimously approved by the Board of Directors of PROS, is expected to close in the fourth quarter of 2025, subject to approval by PROS shareholders, the satisfaction of regulatory approvals and customary closing conditions. Upon closing of the transaction, PROS will be a private company, and its common stock will no longer be listed or traded on the New York Stock Exchange or any public exchange. The Company will continue to be headquartered in Houston, Texas.

Third Quarter 2025 Financial Results

In light of the announced transaction with Thoma Bravo, PROS will not be hosting its third quarter earnings conference call. Third quarter 2025 results will be released at a later date.

Advisors

Qatalyst Partners is serving as exclusive financial advisor to PROS, DLA Piper LLP (US) is serving as legal counsel and Joele Frank, Wilkinson Brimmer Katcher is serving as strategic

communications advisor. Evercore is serving as financial advisor to Thoma Bravo and Kirkland & Ellis LLP is serving as its legal advisor.

Company News

Altair Announces an Agreement with the Polytechnic University of Turin

24 September 2025

Altair, a global leader in computational intelligence, has expanded its partnership with the Polytechnic University of Turin by signing a memorandum of understanding (MoU) to provide all student teams of the university with access to Altair technology. While teams such as Astra, FlyToFuture, H2Fly, H2politO, Icarus, PoliTOcean, Policumbent, PoliTo Rocket, Polito Sailing Team, Squadra Corse, Squadra Corse Driverless, and S55 are already using Altair software, this agreement empowers other teams to benefit from it.

"The expansion and strengthening of our collaboration with the Polytechnic University of Turin is a perfect example of Altair's commitment to students and academic institutions, and to the vital role they play in technology—both today and in the future," said Jim Ryan, vice president, global academic programs, Altair. "Altair takes great pride in offering technology that empowers students to deepen their knowledge, sharpen their skills, and become 'real world ready.' No other company gives students the same opportunity to unleash their creativity and inspire innovation like Altair."

The agreement will grant student team members free access to the Altair® HyperWorks® design and simulation platform and the Altair® RapidMiner® data analytics and artificial intelligence (AI) platform to develop their innovative projects. These solutions will empower students with AI-driven multiphysics and multi-domain simulation capabilities as well as comprehensive data analytics and machine learning tools to manage experimental data. In addition, the agreement also provides access to training tools.

The agreement will allow student teams to strengthen their technical skills in the field of simulation, fostering creativity, drive, and leadership through hands-on experiences and project-based training that lead to the development of functional prototypes.

"The agreement between Altair and Polytechnic University of Turin will allow all student teams of our university to use state-of-the-art simulation tools, supported by expert consultancy. A wonderful opportunity for our students, and we are delighted with this collaboration," said professor Massimiliana Carello, faculty advisor for student teams.

The MoU will further enable students to strengthen their technical and managerial skills and will support student teams, fostering creativity, a drive to achieve, and leadership through hands-on experiences and project-based learning.

Bentley Systems Signs MoUs with Anna University, Kumaraguru College of Technology, and Sri Ramakrishna Engineering College to Advance Digital Infrastructure Skills in India

19 September 2025

Bentley Systems, Incorporated, the infrastructure engineering software company, announced it has signed Memoranda of Understanding (MoUs) with Anna University, Kumaraguru College of Technology (KCT), and Sri Ramakrishna Engineering College (SREC). These partnerships mark a significant step forward in strengthening academia–industry collaboration in India and equipping students with the skills and technologies necessary for the future of infrastructure engineering.

Through its partnerships with the institutions, Bentley will provide students and faculty with free access to its industry-leading digital twin and infrastructure engineering software, including software such as MicroStation, OpenRoads, and OpenFlows, which are widely used in designing and managing complex infrastructure projects.

Bentley will also provide industry-relevant training through its Bentley Education portal, offering self-paced tutorials, certifications, and project-based learning aligned with real-world engineering practices. Students will gain exposure to global best practices by engaging with Bentley Systems' worldwide network of professionals and infrastructure initiatives, while faculty members will receive dedicated resources to seamlessly integrate Bentley software into their curriculum.

The partnerships underscore Bentley's commitment to advancing digital upskilling and supporting India's national initiatives, including Viksit Bharat 2047, by empowering students to apply cutting-edge technology to real-world challenges in water, transportation, energy, and urban development.

Kamalakannan Thiruvadi, Regional Executive, South Asia, Bentley Systems*, said, "India has one of the world's largest talent pools in engineering, and universities play a pivotal role in shaping this workforce. Our MoUs with Anna University, Kumaraguru College of Technology, and Sri Ramakrishna Engineering College are part of Bentley Systems' commitment to nurturing the next generation of engineers through stronger industry–academia collaboration. Together, we aim to inspire innovation, accelerate research, and empower students with practical exposure to digital engineering software."*

"Anna University is committed to equipping students with the skills needed to excel in today's fast-changing engineering environment. Our collaboration with Bentley Systems will offer students hands-on experience with globally adopted technologies, enabling them to make a significant impact in the infrastructure sector," said ***Dr. J. Prakash, Registrar, Anna University, Chennai****.*

"Kumaraguru College of Technology has always emphasised innovation and practical application in engineering education. Collaborating with Bentley Systems will empower our students and faculty with access to industry-grade tools and insights, enabling them to drive

impactful solutions in areas ranging from sustainable design to smart cities," said ***Dr M Ezhilarasi, Principal, Kumaraguru College of Technology, Coimbatore.***

"At Sri Ramakrishna Engineering College, our focus has always been on preparing students to excel in a competitive, technology-driven world. Partnering with Bentley Systems provides our students and faculty the opportunity to learn on globally adopted platforms, gain hands-on exposure to digital infrastructure practices, and strengthen their employability and innovation capacity," said ***Dr. A. Soundarrajan, Principal, Sri Ramakrishna Engineering College, Coimbatore.***

Bluebeam Expands Procore Partnership for Construction Collaboration with Two Powerful Integrations

23 September 2025

Bluebeam, a global leader in solutions and services for architecture, engineering, and construction (AEC) professionals and a part of the Nemetschek Group, announced a strategic partnership featuring two new integrations with Procore, the leading global provider of construction management software. The Procore Documents + Bluebeam and Procore Submittals + Bluebeam integrations are designed to help eliminate data silos, increase efficient workflows, streamline collaborative document reviews, and ensure teams work from a single source of truth across the project lifecycle.

Bluebeam's expanded partnership with Procore underscores a shared commitment to driving innovation and streamlining AEC workflows for mutual customers globally. Building on Bluebeam's recent introduction of its Integrations Directory and key product enhancements, this collaboration strengthens Bluebeam's vision for an open, connected ecosystem that empowers project teams to collaborate seamlessly across the tools they use every day.

Procore Documents + Bluebeam empowers users to add markups directly to files stored in Procore Documents, with all changes automatically saved back to Procore. This helps ensure project stakeholders have access to the latest content, without the risk of version control issues. Files can also be imported into Bluebeam Studio Sessions for quick, multi-user review.

Procore Submittals + Bluebeam connects Bluebeam's powerful markup tools with Procore's Submittals workflow. Teams can launch Bluebeam Studio Sessions directly from Procore, review submittal PDFs collaboratively, and return marked-up documents automatically to Procore – eliminating manual steps and preserving a complete audit trail.

"These integrations remove barriers to collaboration and keep teams focused on building, not managing documents and data," said Luke Prescott, Head of Product at Bluebeam. "By deepening our integrations with Procore, we're removing barriers to collaboration and ensuring that project teams can work more efficiently and accurately. Our goal is to empower construction professionals with tools that keep everyone on the same page, across the project lifecycle."

"Seamless collaboration is critical for driving efficient and successful project delivery," said Geoff Lewis, SVP of Product Management at Procore. "Our expanded integrations with

Bluebeam give customers powerful, connected workflows that reduce friction and ensure everyone is working from the same set of information. Together, we're helping the industry build smarter and faster."

Bluebeam's expanded integration strategy reflects its commitment to connecting leading industry tools and delivering solutions that drive digital transformation in construction.

Other Nemetschek Group brands are also enhancing their connectivity with Procore , including:

Solibri: The new Solibri CheckPoint integration brings advanced, cloud-based BIM model checking and issue management into Procore for real-time validation of Revit® and IFC models.

GoCanvas & SiteDocs: GoCanvas enables automated mobile data collection and safety management workflows within Procore, while SiteDocs links compliance records and safety forms to projects for a unified safety platform.

dRofus: A new workflow between dRofus and Novorender, a Procore company, allows instant visualization of BIM project data within Novorender's 3D environment and direct integration into Procore for comprehensive coordination.

Digital Twin Consortium Welcomes AMD to Accelerate AI-Powered Digital Twin Innovation at the Edge

17 September 2025

Digital Twin Consortium® (DTC) announced that Advanced Micro Devices, Inc. (AMD) has joined as a member. AMD will bring its cutting-edge AI processing capabilities and innovative edge computing solutions to accelerate AI-powered digital twin systems development and deployment across industries.

The addition of AMD is pivotal as the digital twin market rapidly evolves toward intelligent, autonomous systems powered by artificial intelligence. The company's recent breakthrough innovations include AMD Ryzen™ AI series processors and ROCm™ 7 software, the latest evolution of its open-source software platform built to unleash the full potential of AMD Ryzen™ AI and select AMD Radeon™ Graphics systems.

AMD continues to champion open software and platforms, highlighting the context of digital twin Minions and Lemonade as key enablers of next-generation digital twin capabilities. Minions is an agentic framework developed by the Hazy Research Group at Stanford University for collaboration between frontier models running in the data center and smaller models running locally on an AI PC. Lemonade Server is a powerful tool that enables local large language models (LLMs) to run with neural processing unit (NPU) acceleration on AMD Ryzen™ AI 300 Series PCs.

Transforming Digital Twin Intelligence with Edge AI

AMD's participation in the DTC directly supports the consortium's recently announced AI Agent Capabilities Periodic Table (AIA CPT) framework, developed by the Composability Framework team, led by Pieter Van Schalkwyk, CEO of XMPro and co-lead of the AI Joint Working Group,

and Sean Whiteley, CEO and founder of AXOMEM. The company's Ryzen AI technology, through hybrid NPU and integrated GPU architecture, enables the deployment of sophisticated AI agents and Multi-Agent Generative Systems (MAGS) directly at the industrial edge.

"The advanced AI processing capabilities of AMD and its commitment to open, standards-based innovation make them an invaluable addition to our consortium," said Dan Isaacs, GM & CTO of Digital Twin Consortium. "With Ryzen technology and an open-source framework, AMD helps address critical challenges in digital twin intelligence, enabling organizations to deploy sophisticated AI agents locally while maintaining data sovereignty and predictable costs."

"AMD is committed to democratizing AI capabilities and making intelligent computing accessible at the edge," said Dr. Giulio Coradi, AMD Fellow, Principal Architect, Industrial Vision Healthcare & Science, AMD Adaptive and Embedded Computing Group. "Our collaboration with the Digital Twin Consortium will accelerate the development of composable, secure digital twin systems that operate autonomously while seamlessly integrating with industrial infrastructure."

Advancing the Complete Digital Twin Lifecycle

AMD technology enables digital twin systems to manage full lifecycle operations, supporting continuous real-time improvement and optimization. The company's hardware-software integration approach, combining Ryzen AI processors with open-source frameworks, provides the foundation for composable digital twin architectures that can scale from pilot projects to enterprise-wide deployments, such as advanced energy solutions, including SMR and related technologies, advanced manufacturing, robotics/humanoids, and healthcare and life sciences.

"The convergence of edge AI and digital twin technology represents a transformative opportunity for industries worldwide," said Pieter Van Schalkwyk, CEO at XMPro. "As a member of the Digital Twin Consortium, AMD will help accelerate the development of practical, scalable solutions that deliver measurable business value while maintaining the security and reliability that mission-critical operations demand."

Driving Open Standards and Innovation

As a DTC member, AMD will contribute to developing open standards and frameworks that ensure interoperability across digital twin platforms and technologies. The company's commitment to open-source innovation, demonstrated through initiatives like the Lemonade Server and collaboration with academic and research institutions, aligns with the consortium's mission to accelerate digital twin adoption through shared knowledge and best practices.

ENCY Software and Fuzzy Logic Forge Strategic Partnership to Expand Multi-Brand Robot Compatibility

24 September 2025

ENCY Software, a pioneer in industrial robotics software solutions, and Fuzzy Logic, a leader in intuitive robot control technologies, have announced a strategic partnership aimed at reshaping the future of industrial automation.

As part of the agreement, ENCY Software will integrate and distribute Fuzzy Logic's cutting-edge hardware and software, bringing unprecedented compatibility and control to ENCY Hyper, the company's latest solution for programming and simulating industrial robots.

Expanded Compatibility, Enhanced Control

Through this collaboration, ENCY Hyper will now support a significantly broader range of robotic systems. In addition to the in-house developed drivers for KUKA, FANUC, and DOBOT, users will benefit from native compatibility with multi-brand robots including ABB, FANUC, KUKA, Stäubli, Universal Robots, Yaskawa, and FAIRINO — all made possible by the Fuzzy Real-Time Control Module (RTC).

ENCY Hyper: Next-Gen Robot Programming

ENCY Hyper is a next-generation system for programming and simulating industrial robots and auxiliary equipment. It blends the flexibility of offline programming with the responsiveness of real-time methods in a streamlined, touch-optimized workflow designed for tablets and industrial PCs.

Key features include:

- Real-time robot and sensor feedback
- AI-powered auxiliary tools
- Built-in collision avoidance
- Complete digital twin of the robotic cell
- Easy multi-brand robot calibration and programming from a single interface

ENCY Hyper can be used independently for pick-and-place, palletizing, packaging, or assembly — or seamlessly paired with ENCY Robot for advanced applications like milling, welding, spraying, or grinding.

Fuzzy RTC: Precision Real-Time Robot Control, Now Distributed by ENCY

The **Fuzzy Real-Time Control** module delivers low-latency communication, advanced trajectory control, and seamless multi-brand support — all deeply integrated into the ENCY Hyper platform.

With ENCY Software as the technology partner and provider of Fuzzy Logic's solutions, users of ENCY Hyper gain greater precision, faster deployment, and future-proof interoperability — all within a single integrated ecosystem.

What Users Gain

- **Freedom of choice**: Deploy and scale multi-brand robots under one ENCY Hyper interface.
- **Faster commissioning**: Rapid calibration and live feedback tighten iteration loops.
- **Technological flexibility**: Adapt to different robot brands and evolving production needs without retooling.

HCLTech included in Microsoft's 2025/26 AI Business Solutions Inner Circle

25 September 2025

HCLTech, a leading global technology company, has been included in the 2025/26 Microsoft AI Business Solutions Inner Circle, placing it among the top 1% of Microsoft partners worldwide. This highlights HCLTech's exceptional performance in delivering AI-powered business solutions that drive measurable outcomes for global enterprises.

The Inner Circle distinction is awarded to partners who consistently demonstrate innovation, customer impact and excellence in deploying Microsoft technologies — including Dynamics 365, Power Platform, Copilot Studio and Azure OpenAI Service — to accelerate digital transformation.

As an Inner Circle member, HCLTech gains privileged access to Microsoft's senior leadership and strategic roadmap discussions — strengthening its ability to co-innovate and shape the future of AI-powered business transformation.

HCLTech's Microsoft Business Applications Practice is backed by all six Microsoft Solution Partner designations and over 20 specializations, supported by a large pool of certified specialists and engineers. This foundation empowers HCLTech to deliver enterprise-scale AI transformation across industries efficiently.

"This recognition affirms our commitment to building a robust AI ecosystem that delivers agentic automation, operational efficiency and business value at scale," said Pawan Vadapalli, Corporate Vice President and Global Head, Digital Business Services at HCLTech. "Our strategic alignment with Microsoft enables us to bring cutting-edge AI solutions to our clients, helping them stay ahead in a rapidly evolving digital landscape."

Jax State and EOS Partner to Develop Additive Manufacturing Curriculum Through Additive Minds Academy Ignite Program

16 September 2025

Jacksonville State University (Jax State) has partnered with EOS North America's Additive Minds applied engineering group to expand its additive manufacturing (AM) curriculum through the Additive Minds Academy Ignite Program. This collaboration provides Jax State students with access to industrial-grade AM training and resources as part of the university's growing focus on advanced manufacturing technologies.

As part of this initiative, Jax State has also acquired its second EOS M 290 system, an industry-leading laser powder bed fusion (LPBF) metal 3D printer, to provide students with hands-on experience using production-grade AM technology.

The Additive Minds Academy Ignite Program is designed to accelerate AM education and workforce development by offering scalable, structured online and hybrid learning solutions. It supports educational institutions in teaching the fundamentals and applications of industrial 3D printing, including machine operation, safety, design for AM, production strategies, and more.

"We're excited to deepen our commitment to additive manufacturing education through the Ignite Program - by combining EOS's industrial training resources with our expanding AM lab and faculty expertise, we're preparing students for real-world careers in advanced manufacturing and giving them the skills they need to succeed in this rapidly growing field. With the addition of our second EOS M 290, our AM assets now total more than $3 million, underscoring our commitment to being a leader in advanced manufacturing innovation and workforce development."
Matt Rosser, Director of the Center for Manufacturing Support at Jax State

Jax State joins the University of Illinois Urbana-Champaign and Columbia Gorge Community College as one of the first universities to adopt the newly launched Ignite Program. It is also used by Launch Canada, a national nonprofit that supports aerospace innovation and hosts Canada's largest student rocketry competition, where students train in Design for Additive Manufacturing (DfAM) through the Ignite programming.

The Ignite Program offers two flexible tiers based on a university's access to EOS systems:

- **AM Fundamentals** provides access to online courses such as:
    - Getting Started with Industrial 3D Printing
    - Design for Additive Manufacturing
    - Material Science
    - System Process Control
- **Certification Partner** provides access to AM Fundamentals content and:
    - EOSPRINT 2 Introduction
    - Process Science & Engineering Certificate Program
    - Local EOSPRINT SW licenses
    - System Operation Certification enablement
    - Partner Operator Certification for students upon completion of training

"*The Ignite Program was built to bridge the gap between industrial needs and education - by collaborating with innovative institutions like Jax State, we're empowering the next generation of engineers with the skills and confidence to contribute meaningfully to the future of additive manufacturing,*" said Fabian Alefeld, Global Director of Business Development and Additive Minds Academy at EOS.

JBT Marel Unveils 2024 Sustainability Report, Showcasing Dedication to Positive Environmental and Social Impact

18 September 2025

JBT Marel Corporation, a global leader in food and beverage technology solutions, released its 2024 Sustainability Report, "Shaping the Future of Food Together." The report highlights how

the company creates meaningful impact for customers, employees, communities, and the wider food ecosystem.

"Sustainability is more than a goal—it's a responsibility," said Brian Deck, Chief Executive Officer. "Every step we take today defines the kind of company we will be tomorrow. Together, JBT Marel's diverse solutions, enhanced operational scale, and deep application, service, and digital expertise expand our ability to support customers and the global food system."

JBT Marel's Sustainability report reflects our clear purpose: To Transform the Future of Food. Hunger, malnutrition, water scarcity, carbon emissions, and climate change are among the most pressing challenges of our time. JBT Marel is uniquely positioned to address these challenges, guided by five key pillars:

- **Customers:** JBT Marel is focused on delivering advanced, proven, and complementary machine and digital technologies. With broad and holistic offerings spanning diversified end markets, including proteins, beverages, fruits and vegetables, and pet food, the company is committed to driving the next level of equipment performance, line productivity, operational efficiency, and sustainability for customers worldwide.
- **People and Communities:** Our people are the true drivers of innovation and performance. JBT Marel is a global, diverse, and motivated group, united to make a difference. In 2024, the company began developing a new diversity, equity, inclusion, and belonging (DEIB) governance structure, which includes executive oversight and further embeds DEIB across the business. JBT Marel is also building a culture hub to house DEIB-related initiatives, including employee network communities and site- and region-specific programs, ensuring they reflect and support the company's global workforce.
- **Operations:** Efficiency is at the core of JBT Marel's approach, driving continuous improvements to optimize operations, minimize environmental impact, and strengthen business resilience. We are aligning best practices, combining policies and programs and evaluating opportunities to set environmental targets.
- **Supply Partners:** JBT Marel's global supply chain is central to consistently meeting and exceeding customer expectations. With suppliers worldwide, the company focuses on establishing a standard of ethical behavior that goes beyond compliance and legal obligations. JBT Marel engages with suppliers to better understand their environmental impact. The company recently released a new Supplier Code of Conduct that establishes the expectations of its supply partners.
- **Governance:** JBT Marel is committed to operating with integrity for the benefit of its employees, customers, communities, and other stakeholders. The company's Guide to Ethical Conduct sets clear expectations for employees, promoting ethical and responsible conduct in the workplace and ensuring alignment with company values. The company is also in the process of combining its legacy double materiality assessments, mapping the sustainability issues most critical to its business and areas where its

operations have the greatest impact, allowing JBT Marel to shape its long-term sustainability strategy.

At its core, JBT Marel is a purpose-driven company, trusted by employees, customers, and stakeholders to deliver transformative solutions and services while operating responsibly and innovatively.

L&T Technology Services Joins the MIT Media Lab to Collaborate on AI-led Innovations

19 September 2025

L&T Technology Services, a global leader in AI, Digital & ER&D Consulting Services, announced a multi-year membership agreement with the MIT Media Lab, one of the world's most prestigious research institutions. As a consortium Lab Member, LTTS intends to explore next-generation advancements in artificial intelligence (AI), underscoring its commitment to driving transformational innovation in Mobility, Sustainability and Tech.

As part of the agreement, LTTS will engage in active discussions and information exchange with the Media Lab's unique cross-disciplinary ecosystem that brings together researchers, innovators and industry leaders.

The collaboration not only emphasizes practical AI innovation but also accelerates technology-driven advancements by linking LTTS' expertise in AI and engineering with the Media Lab's unique research approach. Together, they intend to explore sustainable engineering solutions that redefine industries, from creating smarter mobility systems to rethinking infrastructure for a greener future.

"*We are delighted to join the MIT Media Lab, a dynamic and creative interdisciplinary research sandbox," said* ***Amit Chadha, CEO & Managing Director, L&T Technology Services****. "This collaboration underscores LTTS' commitment to pushing the boundaries of engineering excellence. From exploring Agentic AI to early AGI application roadmaps, we are setting a course to shape the future of industries reliant on Mobility, Sustainability and Tech."*

For over four decades, the MIT Media Lab has pioneered transformative research at the intersection of art, science, engineering, and design, redefining technologies and experiences that enable people everywhere to flourish. By joining this dynamic environment, LTTS strengthens its mission of building purposeful, agile, and sustainable engineering innovations for its global client base.

"At the MIT Media Lab, we thrive on relationships that bring together bold industry leaders with our community of researchers," said ***Jessica Rosenworcel, Executive Director of the MIT Media Lab****. "Collaborating with LTTS opens exciting opportunities to engage with AI, data, and design thinking in addressing real-world challenges in mobility, sustainability, and technology. Together, we're exploring the boundaries of what's possible to inspire meaningful impact at a global scale."*

LTTS will also host its flagship industry programs, including the Digital Engineering Awards (DEA) and Advisory Council gatherings, at the MIT Media Lab. These events will act as incubators for

LTTS' business collaborators leading global R&D activities — supporting roadmap development, knowledge exchange, and accelerated technological breakthroughs.

L&T Technology Services, Siemens Partner for AI-led Transformation in Process Engineering & Smart Manufacturing

26 September 2025

L&T Technology Services, a global leader in AI, Digital & ER&D Consulting Services, announced an expanded partnership with Siemens Limited, a leading technology company focused on industry, infrastructure and mobility. This collaboration aims to advance Machine & Line Simulation and IIoT Technology, setting a new benchmark for innovation within LTTS' Sustainability segment, which encompasses Process Engineering, Discrete Manufacturing and Industrial Products.

Through this alliance, LTTS will utilize the digital technology portfolio of Siemens Limited to deliver simulation-driven automation and IIoT-enabled solutions for diverse sectors including Automotive & Transportation, Industrial Products, and Process & Plant Engineering. By combining Siemens' flagship platforms, TIA Portal, Industrial Edge, and Tecnomatix, integrated with LTTS' AI-driven engineering expertise, the partnership will accelerate digital adoption, improve precision in system design, and drive faster, smarter decision-making across manufacturing ecosystems.

Building on a decade of collaboration and engineering excellence, LTTS is driving transformation across the process engineering domain and helping enterprises achieve greater agility and resilience. From enhancing design accuracy to enabling predictive and sustainable production at scale, the strengthened partnership positions LTTS at the forefront of creating intelligent and environmentally responsible industrial ecosystems worldwide.

Our collaboration with Siemens underscores a shared vision of driving AI-powered innovation and operational excellence across industrial ecosystems," ***said Alind Saxena, President & Executive Director - Mobility & Tech, L&T Technology Services****. "By focusing on robust solutions such as Machine & Line Simulation and IIoT Technology, we are empowering industries to achieve greater agility, actionable insights, and measurable business outcomes."*

Suprakash Chaudhuri, Head of Digital Industries, Siemens Limited, added*, "At Siemens, we believe that partnerships are the cornerstone of the digital transformation journey for Indian enterprises. By combining deep domain expertise with cutting-edge digital solutions, we can co-create scalable, future-ready innovations that empower industries to thrive in a rapidly evolving world. We are delighted to welcome LTTS as our Solution Partner and look forward to shaping the future of digital transformation together."*

Oracle Corporation Announces Promotion of Clay Magouyrk and Mike Sicilia to CEOs; Safra Catz Appointed Executive Vice Chair of the Board of Directors

22 September 2025

Oracle Corporation announced the promotion of Clay Magouyrk and Mike Sicilia to the roles of Chief Executive Officers.

Clay Magouyrk, previously President, Oracle Cloud Infrastructure (OCI), joined Oracle in 2014 from Amazon Web Services. As a founding member of Oracle's cloud engineering team, Clay has overseen the design, implementation and business success of Gen2 of OCI. Oracle Cloud Infrastructure Gen2 is a high-performance, secure, cost-efficient platform that powers both hyperscale public cloud datacenters and gigawatt-scale AI Training datacenters. Under his leadership, OCI has achieved unprecedented growth and has become the go-to platform for AI training and inference.

Mike Sicilia, formerly President, Oracle Industries, brings deep expertise in vertical applications and applied AI. Joining Oracle through the acquisition of Primavera Systems, Mike's engineering teams pioneered the use of intent-based application generation to replace traditional coding for building Oracle applications. His teams also added very sophisticated sets of AI Agents to our industry application suites—including healthcare, banking, communications, utilities, hospitality and retail. These new AI cloud applications deliver comprehensive, end-to-end solutions to both regulated and traditional industries.

Larry Ellison, Oracle's Chairman of the Board and Chief Technology Officer, stated, "Humanity is investing enormous resources in the race to advance Artificial Intelligence. Oracle Cloud Infrastructure is playing a major part in that effort. Clay's years of experience leading Oracle's large, fast-growing Cloud Infrastructure business has demonstrated his readiness for a CEO role. Mike has spent the last several years modernizing Oracle's Industry applications businesses—including Oracle Health—by completely rebuilding those applications using the latest AI technologies. A few years ago, Clay and Mike committed Oracle's Infrastructure and Applications businesses to AI—it's paying off. They are both proven leaders, and I am looking forward to spending the coming years working side-by-side with them. Oracle's future is bright."

Together, CEOs Magouyrk and Sicilia will continue to collaborate on building complete industry suites of AI applications on top of Oracle's rapidly evolving AI Database and Cloud Infrastructure. "We are excited to lead Oracle into the AI era, where technological innovation leads to extraordinary business opportunity and hyper-growth," said Magouyrk and Sicilia in a joint statement. "Our combined strengths in AI, cloud infrastructure, horizontal applications and industry applications, will enable Oracle to deliver the latest AI capabilities to our customers."

Safra Catz, who has served as Oracle's CEO since 2014, has been appointed to serve as Executive Vice Chair of the Oracle Board of Directors. Larry Ellison, Oracle's Chairman of the Board and Chief Technology Officer, said, "Safra led Oracle as we became a hyperscale cloud powerhouse—clearly demonstrated by our recent results. In her role as Vice Chair, Safra and I will be able to continue our 26-year partnership—helping to guide Oracle's direction, growth and success."

"Today, Oracle is recognized as the cloud of choice for both AI training and inferencing. I'm very proud of that," said Safra Catz. "Oracle's technology and business have never been stronger.

And our breathtaking growth rate points to an even more prosperous future. At this time of strength is the right moment to pass the CEO role to the next generation of capable executives. Congratulations Clay and Mike."

Oracle also announced that Mark Hura, currently EVP of Oracle North America Sales, is being promoted to President, Global Field Operations. Doug Kehring, current EVP of Operations, is being promoted to Principal Financial Officer.

The company also reaffirmed the financial guidance provided on its September 9, 2025, earnings conference call.

Oracle will host a conference call and live webcast at 8:00 a.m. Central Time to discuss today's announcement. The live webcast will be available on the Oracle Investor Relations website at www.oracle.com/investor.

Procore Announces Appointment of Ajei Gopal as Chief Executive Officer

22 September 2025

Procore Technologies, Inc., the leading global provider of construction management software, announced the appointment of Ajei Gopal as Chief Executive Officer Designate, and a member of the company's Board of Directors. Gopal will succeed Procore's Founder, President, and CEO Tooey Courtemanche following the public announcement of the company's Q3 financial results, with an anticipated start date of November 10, 2025. Courtemanche will then transition out of operational responsibilities and focus on his role as Chair of the Board of Directors.

Gopal has over 35 years of proven experience leading global technology companies at scale, most recently serving as the President and CEO of Ansys, Inc. from 2017 to 2025. Under Gopal's leadership, Ansys more than tripled its revenue, nearly quadrupled its market value, and became the global leader in engineering simulation–joining the ranks of the S&P 500 and NASDAQ 100, and earning international recognition as a top employer. Gopal's tenure at Ansys culminated in leading the company through its $35 billion acquisition by Synopsys, Inc., after which he was appointed to Synopsys's Board of Directors.

Prior to Ansys, Gopal held senior leadership positions at Hewlett-Packard, CA Technologies, and Symantec, served as an operating partner at Silver Lake, a leading private equity technology investment firm, and founded the start-up ReefEdge Networks. Together, these experiences have shaped him into a versatile leader who knows how to scale innovation, navigate complexity, and deliver lasting impact.

"Procore is one of the most transformative companies in the market today. Its award-winning platform and culture have cemented its status as the clear category leader, revolutionizing one of the world's most essential yet least digitized industries," said Gopal. "Like Tooey, I'm passionate about empowering people to build the physical world through digital innovation and am deeply inspired by the industry's sense of purpose and Procore's deep customer-centricity. Tooey has built a truly exceptional company, and I couldn't be more honored that he and the Board have put their trust in me to lead Procore through its next phase of growth."

"I am incredibly proud of what we've built at Procore over the past 25 years," said Courtemanche. "It's a testament to the dedication of our employees and the partnership of the industry that I love. We've found an exceptional leader in Ajei, who understands that Procore does more than build software—we're a mission-driven platform empowering people to build the places that shape our world. Ajei's experience leading a vertical software company to billions in revenue uniquely positions him to help us scale and capture the opportunity ahead. I am excited about what's next and look forward to supporting Ajei in my role as Chair, where my commitment to our customers, the industry, and Procore's success will remain as strong as ever."

"On behalf of the Board of Directors, I am thrilled to welcome Ajei as Procore's next CEO," said Graham Smith, Lead Independent Director. "Ajei's extensive experience and track record of driving efficient growth, innovation, and operational excellence at world-class technology organizations make him exceptionally well-suited to guide Procore into the future and continue to deliver value for all of our stakeholders. I also want to express our deepest gratitude to Tooey for his visionary leadership in building Procore from an idea into one of the most widely used construction management platforms in the world and transforming the way construction gets done."

Procore reaffirms its third quarter fiscal 2025 and full-year fiscal 2025 guidance, as previously announced in its earnings release for its second quarter 2025 financial results on July 31, 2025.

PROSTEP - Collaboration with Wecon PLM on AI-based software testing

26 September 2025

PROSTEP and Wecon PLM, an IT consulting company and service provider that specializes in software development, test and project management, will in the future collaborate more closely on customer projects. PROSTEP will market Wecon PLM's RelAIable software for automating software testing and provide customers with support when integrating the solution in their IT landscapes. The joint offering is aimed not only at big-name customers in the automotive industry, who for example want to check whether or not the customized user interfaces for their PLM or ALM solutions are functioning correctly. It is also aimed at machine and plant manufacturers as well as medical equipment manufacturers, who are faced with the challenge of continuously improving the operation of their machines and devices.

Testing graphical user interfaces is one of the most important and time-consuming tasks involved in software development. It is difficult to automate testing using conventional methods, which is why testing is usually performed by offshore or nearshore teams. Wecon PLM has developed software for this purpose that automates the processing of test cases with the help of artificial intelligence (AI). The software can be used to test both web and desktop interfaces as well as apps for mobile devices.

RelAIable makes it possible to generate scripts for testing graphical user interfaces based on natural language specifications using multimodal large language models (LLM) and to automatically adapt these scripts when changes are made. The test cases can be specified directly in RelAIable or imported from tools like Xray. The software can be integrated

seamlessly in all leading test management environments such as JIRA/Xray, ALM Octane and Azure DevOps Server.

The software for automating testing was actually designed as a SaaS solution, but it can also be installed on-premises. "When testing user interfaces for big-name customers, confidential data is almost always involved. We have therefore designed the tool chain to run on site at the customer's premises and use their AI infrastructure and/or language models. This is a key unique selling point as it protects their intellectual property and makes it easier for them to comply with data protection regulations", as Bernd Weber, managing director of Wecon PLM, points out.

PROSTEP and Wecon PLM have already worked together successfully on a number of projects for BMW. "This gave rise to the idea of stepping up this collaboration for the mutual benefit of both companies," says Norbert Lotter, Head of Near- and Offshore Operations at PROSTEP, commenting on the collaboration. "We are currently carrying out a proof of concept (POC) at another German carmaker with the aim of demonstrating the potential for automation and savings using real-life use cases."

The use of RelAIable helps simplify the testing of user interfaces dramatically and reduce related costs. Time savings of up to 90 percent – especially in the case of automatically "repairing" test scripts following software changes – make continuous testing and a fast return on investment possible.

SAP and OpenAI Partner to Launch Sovereign OpenAI for Germany

24 September 2025

SAP SE and OpenAI announced the launch of OpenAI for Germany, a partnership to bring SAP's enterprise applications expertise and OpenAI's leading AI technology to Germany's public sector.

To ensure sovereignty, OpenAI for Germany will be supported by SAP's subsidiary Delos Cloud, running on Microsoft Azure technology. The collaboration will enable millions of public sector employees to use AI safely and responsibly while meeting strict data sovereignty, security, and legal standards.

Christian Klein, CEO of SAP SE, said, "Applied AI is what truly creates value. As a Business AI company with decades of experience serving public sector organizations, we believe OpenAI for Germany represents a huge step forward. We're bringing together SAP Sovereign Cloud expertise with OpenAI's leading AI technology to pave the way for AI solutions that are built in Germany, for Germany."

Sam Altman, CEO of OpenAI, said, "Germany has long been a pioneer in engineering and technology, so it's no surprise that millions of Germans already use ChatGPT to make their lives easier, drive scientific breakthroughs, and build new businesses. With OpenAI for Germany, we'll work with local partners to extend this potential to the public sector—helping to improve services and ensuring that the benefits of AI are shared across the country, and doing so in line with German values of trust and safety."

Satya Nadella, Chairman and CEO of Microsoft, said, “With this partnership we are looking forward to bringing more AI capabilities to Germany’s public sector. Azure as the platform for Delos Cloud will power this, helping to ensure AI is deployed with the highest standards of sovereignty, data privacy, regulatory compliance, and operational resilience—empowering public institutions to adopt AI confidently and responsibly.”

Through this collaboration, planned for launch in 2026, OpenAI, SAP and Microsoft will focus on helping employees in German governments, administrations and research institutions accelerate their daily work and spend more time on people, not paperwork. OpenAI for Germany also serves as a cornerstone for developing customized public sector applications and integrating AI agents directly into existing workflows to automate and improve processes such as records management and administrative data analysis.

In support of this approach, SAP plans to expand the existing infrastructure of Delos Cloud in Germany to 4000 GPUs for AI workloads. Subject to future demand, SAP plans to further invest in applied AI capabilities in Germany, scaling through existing SAP-owned infrastructure as well as through new collaborations with co-location providers and other partners. These efforts aim to extend the sovereign offering to additional industries and markets across Europe.

OpenAI for Germany directly supports Germany’s national AI ambitions. The German Federal Government’s High-Tech Agenda targets AI-driven value creation of up to 10% of GDP by 2030, signaling a major push to adopt AI across the economy and public sector. Meanwhile, the “Made for Germany” initiative, which is now backed by 61 leading companies and global investors, including SAP—has pledged more than €631 billion in investments to accelerate growth and modernization. SAP also recently announced an investment of more than €20 billion to strengthen Germany’s digital sovereignty.

Siemens and Machine Builders Agree on Groundbreaking Data Alliance

23 September 2025

Siemens and several leading machine tool manufacturers – including Grob, Trumpf, Chiron, Renishaw, and Heller, along with the Machine Tool Laboratory (WZL) of RWTH Aachen and the Voith Group – formed a groundbreaking alliance that provides for a systematic exchange of engineering, manufacturing and machine data that will be used to develop new generative AI applications for industrial environments. This collaboration marks a decisive step toward the realization of an industry-specific AI model, the Siemens Industrial Foundation Model. Siemens first presented its vision for this model at Hannover Messe 2025.

"Along with our customers and partners, we are taking a significant step today to scale industrial AI. I see a great opportunity here for the European economy and its strong industrial base – from automotive, chemicals, and pharmaceuticals to mechanical engineering, energy, healthcare, infrastructure, and transport among others. By making our companies’ unique data treasure available to create generative AI models, we can achieve totally new levels of productivity – and this data alliance in the machine-building industry is leading the way," says Roland Busch, CEO of Siemens AG.

The alliance intends to significantly increase efficiency and innovation cycles in the manufacturing industry with the targeted use of AI technologies. One conceivable use case in the field of machine tools is the automated creation of a part program for machine tools. These programs could be created significantly faster, while the error rate in code creation is reduced. In addition, programmers will be relieved of basic tasks and can focus on more complex challenges.

"Access to high-quality machine data from different manufacturers is the key," Busch explains. "With this alliance, we can develop AI systems that reflect the complexity entailed in development and manufacturing, and so it will become a powerful partner for skilled workers."

The partnership involves the exchange of anonymized machine data in strict compliance with data protection and security standards. Among other things, the data will be used to develop and train AI models specifically tailored to the requirements of industrial manufacturing. The data from the alliance will be used to automatically create NC programs: a kind of "work instruction" for special manufacturing machines. Other use cases include predictive maintenance with precise machine-specific forecasts, adaptive manufacturing processes that adapt in real time to changing conditions, and energy-efficiency optimization through the intelligent control of machine parameters.

The alliance's long-term strategy includes bringing more companies on board – even beyond the machine tool industry – to leverage industrial artificial intelligence across different industries.

SolidCAD Expands Portfolio with GoCanvas and SiteDocs, Delivering Safety and Compliance Innovation to Canadian Worksites

22 September 2025

SolidCAD, a leading Canadian technology consulting firm, announced a strategic portfolio expansion through partnerships with GoCanvas and SiteDocs, bringing advanced compliance, health, and safety management solutions to organizations across Canada.

GoCanvas, part of the renowned Nemetschek Group parent company to technology brands like Bluebeam, empowers field teams to move beyond outdated paper-based processes with digital data capture, GPS tracking, and connected workflows. As Bluebeam’s only Sapphire Partner in Canada, SolidCAD is uniquely positioned to extend these solutions to current Bluebeam clients while also expanding into the broader health and safety space. Through GoCanvas offerings such as SiteDocs, SolidCAD can also deliver dedicated compliance solutions that support safety leaders and EHS professionals in building safer, audit-ready workplaces.

Through this partnership, SolidCAD strengthens its ability to provide connected, integrated solutions that bridge design, data, and compliance. Bluebeam users will soon be able to seamlessly connect GoCanvas workflows with Bluebeam Revu, enabling teams to assign tasks, dispatch forms, track real-time status, and link submissions back to Revu markups for streamlined documentation.

"Most of our clients in construction, utilities, and manufacturing are still relying on pen and paper for compliance and safety management," said Marcus Tateishi, President at SolidCAD. "With GoCanvas and SiteDocs, we are delivering modern, digital solutions that not only improve compliance and support COR certification but also protect the health and safety of every worker in the field. Combined with Bluebeam, these tools give Canadian firms the technology ecosystem they've been asking for, while opening the door to serve the broader health and safety sector with purpose-built compliance technology."

SiteDocs, part of the GoCanvas portfolio, adds specialized safety compliance management capabilities, including digital safety forms, real-time dashboards, analytics, and audit-ready reporting. Its strong alignment with Canadian workplace standards makes it a natural fit for organizations that must meet COR certification and other compliance requirements.

SolidCAD's expanded offering will be further showcased at Bluebeam's Unbound event in Washington, DC from September 30 to October 2, where attendees will get an exclusive look at the connection points between Bluebeam, GoCanvas, and SiteDocs, and the transformative impact these solutions can have on project delivery, compliance programs, and worker safety.

"There's been a lack of innovation in the compliance and safety space," added Jon Coley, SVP, of Sales at GoCanvas. "By partnering with GoCanvas and SiteDocs, SolidCAD is filling that gap, bringing powerful technology solutions to the Canadian market and helping businesses transition away from manual, paper-driven processes."

Trace One Appoints Séverine Tourpin as Chief Executive Officer

22 September 2025

Trace One, a global leader in Product Lifecycle Management (PLM) and compliance solutions, announced that Séverine Tourpin will serve as its new Chief Executive Officer, succeeding Christophe Vanackère. The transition has been seamless, maintaining full support for our customers.

Séverine takes the helm at a pivotal moment. With over 25 years in PLM, SaaS, and product software, she has successfully led fast-growing SaaS businesses serving diverse and global customer bases and driving international expansion at scale.

Having held executive leadership roles at Trace One in the past, she brings experience and comprehensive knowledge of the organization. Her return ensures continuity and momentum as the company accelerates its global strategy, guided by our mission of empowering brands to accelerate their digital transformation, deliver products of exceptional quality, and create meaningful impact for customers and communities.

Under her leadership and with the support of Main Capital who invested in Trace One earlier in 2025, the company will reinforce its focus on delivering increased value to customers, enhancing innovation, and scaling internationally.

Séverine Tourpin, CEO of Trace One, said: "I'm honored to lead Trace One as we begin this next chapter. My focus will be on offering more value to our customers, improving the user

experience for our community of more than 9,000 brands, and continuing our international expansion alongside our talented teams."

Event News

Cummins, Honda, SLB, Medtronic, and more: ESTECO Users' Meeting North America 2025 agenda announced

18 September 2025

ESTECO is pleased to announce the agenda for the 9th edition of the biennial **ESTECO Users' Meeting North America**, taking place on **October 14-15, 2025**, at Saint John's Resort in Plymouth, MI. This year's event features prominent speakers from leading companies such as **Cummins, SLB, Honda Development & Manufacturing of America, Medtronic, Ford Motor Company**, and **Stellantis North America**.

The event will bring together engineers using ESTECO digital engineering solutions, allowing them to share their experiences and demonstrate **how VOLTA and modeFRONTIER are driving innovation** across various industries. Attendees will have the opportunity to connect with ESTECO experts, discover **new features and upcoming advancements**, and enhance their understanding of ESTECO Technology through interactive workshops.

A significant portion of the agenda is dedicated to the **automotive sector,** traditionally one of the industries where ESTECO Technology is most widespread:

- **Bob Tickel**, Director of Multidisciplinary Simulation, Research and Technology at **Cummins** will discuss how his company's OAR (optimization, automation and robustness) initiative impacts simulation-based product development.
- **Tarek Belgasam**, CAE Principal Materials Research Engineer at **Honda Development & Manufacturing of America**, will focus on AI capabilities enhancing a digital twin framework for virtual quality assessment.
- **Peter Kowalow**, Technical Expert – Parametric/Non-Parametric Optimization, will present how modeFRONTIER contributes to elevating product design at **Ford Motor Company**.
- **Ramachandra Bhat**, Lead Engineer at **Stellantis North America**, will share a use case on workflow standardization for side closures.

The event will also feature contributions from the **energy and biomedical industries**:

- **Amandine Battentier**, Global Technology Modeling & Simulation Manager at **SLB**, will showcase how their Simulation Process and Data Management approach, leveraging modeFRONTIER and VOLTA, has achieved a 40% reduction in simulation time.
- **Arric E. McLauchlan**, Principle Design Automation Engineer at **Medtronic PLC**, will explore the current and future role of Digital Engineering platforms in improving in silico clinical trial evidence and patient-specific care.

ESTECO experts will deliver talks covering recent developments and future innovation drivers such as **Artificial Intelligence** and **data-driven modeling**, **democratization** in simulation, **digital thread** integration, and the connection between **MBSE requirements** and Multidisciplinary Design Optimization (MDO) workflows. A special focus will be on VOLTA cloud deployment, with a joint talk by **Matteo Francia**, Head of Customer Support & Success at ESTECO, and **Sandeep Sovani**, Global GTM Head of Engineering Simulation HPC at **Amazon Web Services**. Their discussion will highlight how the partnership with AWS will be key to streamlining installation procedures and transforming simulation capabilities.

On the second day, October 15, attendees can further explore some of these topics through **dedicated, hands-on workshops**.

Full agenda: um25.esteco.com/north-america/agenda

Registration: um25.esteco.com/north-america/registration

IMAGINiT Technologies Showcases Field-to-Office Workflow Innovations at Bluebeam Unbound 2025

24 September 2025

At the Bluebeam Unbound Conference, IMAGINiT Technologies, a division of Rand Worldwide and a Bluebeam Platinum Partner, will showcase its latest field-to-office workflow innovations. The conference, taking place September 30–October 2, 2025, in Washington, D.C. features IMAGINiT experts who will challenge architecture, engineering, construction firms and owners to rethink collaboration, redefine project outcomes, and accelerate their digital initiatives. As a Silver Sponsor of the conference, IMAGINiT will have a team of experts on hand in Booth #201.

“A company’s digital evolution is more than a technology shift—it’s about connecting enterprise data and platforms resulting in more efficient projects giving our customers a competitive edge,” said Bill Zavadil, president and chief operating officer of IMAGINiT Technologies. “Our partnership with Bluebeam combines the best collaboration technology with IMAGINiT’s deep Autodesk software expertise and services, providing a single trusted partner to improve workflows, deliver stronger project outcomes, and reduce risk. Bluebeam Unbound is the ideal venue to demonstrate the impact of this partnership.”

IMAGINiT Breakout Session

Led by IMAGINiT’s Tom Coons and Lisa Stine, on Wednesday, October 1 at 4:00 PM, this session will show how IMAGINiT’s FormsConnected streamlines field-to-office workflows by eliminating paperwork, reducing risk, and improving visibility through Autodesk Construction Cloud (ACC). Attendees will learn from real-world examples where FormsConnected has delivered measurable gains such as faster work order processing, reduced administrative overhead, and real-time material tracking.

During the session entitled, *“Enhancing Field to Office Workflows with FormsConnected,”* attendees will see how the FormsConnected integration with ACC helps teams:

- Automate data collection to eliminate paperwork
- Standardize checklists and reports to support compliance and safety
- Provide real-time data access for better communication
- Track progress to boost efficiency and reduce delays

IMAGINiT Networking Reception

To welcome Bluebeam Unbound attendees, IMAGINiT will be hosting a kickoff mixer on Tuesday, September 30, from 4:00–6:00 PM in the mezzanine at Bistrot du Coin (1738 Connecticut Ave NW, Washington, D.C.) where you can connect with peers and IMAGINiT experts while enjoying refreshments. Registration for this exclusive event is required.

Introducing OASIS.AI – The Latest AI-based Design Exploration Engine

25 September 2025

October 1 , 2025
11:00 AM (Eastern US)

Register For Webinar Series

With the surge of AI technologies reshaping our society in just the past few years, the engineering community is anxious to understand how these advancements will transform their workflows. Will AI-driven innovation come mainly from their software vendors, or do they also need to directly engage in its development and implementation? This webinar explores the latest developments in the **AI-based design exploration technology** captured in the **OASIS.AI** software to serve the needs of both software providers and end users.

The term **"optimization"** has seen a sharp resurgence in engineering media since the rise of tools like ChatGPT. However, for many, it still carries baggage from the 1990s, when limited computing resources and a lack of understanding led to unrealistic expectations and inconsistent and sometimes doubtful results. Optimization remains a technically demanding domain, requiring the handling of diverse variable types, high-dimensional design spaces, complex constraints, and multi-objective scenarios. While numerous algorithms have been developed over the years to address these challenges—often tailored to specific use cases—their sheer variety has created confusion about which methods to use, slowing widespread adoption.

After decades of research in AI-based learning algorithms, EmpowerOps has developed a comprehensive yet highly efficient automated exploration capability that is easy for users to adopt. In this presentation, EmpowerOps will discuss the latest advancements in its AI-based exploration engine, OASIS.AI, which extends traditional optimization paradigms into broader exploration, enabling engineers to evaluate "what if" scenarios and make use of historical data. This new AI approach efficiently handles highly complex scenarios, leveraging advanced search techniques and small data learning technologies refined over many years. Its robustness and efficiency have been validated across a wide range of benchmark cases, positioning it as a next-

generation tool for optimization and exploration—ready to be embedded in OEM software through partnerships with EmpowerOps or directly utilized by end users.

Presenters

Mike Sheh, PhD, Managing Director, Empower Operations Managing Director, INTES NA
Dr. Mike Sheh has held a variety of technical and management roles across the engineering and computing fields. He began his career as a CAE engineer at General Motors and later moved into the supercomputing sector, working as a specialist at Cray Research and SGI. His interest in engineering optimization led him to join Engineous Software, the developer of *iSIGHT*, one of the earliest commercial tools for Process Integration and Design Optimization (PIDO). Since then, he has actively advocated the application of optimization methods across a broad range of engineering and non-engineering domains.

In 2020, after leaving Dassault Systèmes, he participated in Empower Operations Corp. as Chief Strategist. In this role, he contributes to positioning the company's AI-based exploration engine, *OASIS.AI*, with the goal of making next-generation exploration technologies more accessible and broadly adopted.

Register For Webinar Series

MathWorks Showcases RF System Design and Satellite Communications Expertise at European Microwave Week 2025

21 September 2025

MathWorks, the leading developer of mathematical computing software, will exhibit at the upcoming European Microwave Week (EuMW) 2025 in Utrecht, Netherlands. EuMW is Europe's premier microwave, RF, wireless, and radar event, bringing together thousands of engineers, researchers, and industry leaders. Attendees are invited to visit MathWorks at Booth A094 to explore interactive demos and attend a short course focused on emerging satellite communication and non-terrestrial network (NTN) technologies. To schedule a meeting with MathWorks at EuMW, visit mathworks.com/company/events/tradeshows/european-microwave-week-2025-form.html

"Attendees will gain practical insights into how MATLAB® and Simulink® streamline RF system design — from antenna modeling and signal processing to hardware prototyping," said Giorgia Zucchelli, Principal Product Manager, RF and Mixed-Signal, MathWorks. "Our booth demos and short course will showcase how engineers can reduce development cycles, improve system performance, and apply integrated modeling techniques to real-world challenges in radar, satellite communications, and wireless communications systems."

EXHIBIT BOOTH DEMOS (Booth A094)

MathWorks will present three hands-on demonstrations that highlight how MATLAB and Simulink support the design and simulation of advanced RF and wireless systems.

- *Antenna-to-Bits: RF System Design from Antenna to Bits*
  Model and simulate wireless communications and radar systems from antenna to bits,

including large antenna arrays, RF transceivers, PCB boards, data converters, DSP algorithms, and control logic. Learn how to build a digital twin to evaluate propagation scenarios and explore implementation tradeoffs.

- *OFDM-Based Radar Sensing with USRP Radios*
  Perform range-Doppler processing using a custom OFDM waveform transmitted via NI Ettus USRP E320 radios. MATLAB controls the signal loopback and bistatic processing, with visualizations showing target motion and algorithm performance.
- *Satellite Communications: Modeling Non-Terrestrial Networks (NTNs)*
  Simulate LEO satellite constellations, onboard antennas, signal propagation channels, and receiver architectures. Discover the value of integrated modeling for next-generation SatCom systems.

NEW MODELITHICS LIBRARY FOR MATLAB

MathWorks and Modelithics announced the launch of the new Modelithics Library for MATLAB, featuring Microwave Global Models™ for nearly 28,000 components from over 30 leading suppliers. These models integrate with RF Toolbox™ in MATLAB to support the design of filters, matching networks, amplifiers, and more.

Advanced features include substrate scaling, part value scalability, and de-embedding — offering a flexible alternative to traditional S-parameter files. Engineers can now use MATLAB to simulate RF component behavior with greater accuracy and efficiency.

SHORT COURSE

Architecture and Applications for Emerging SATCOM and NTN Communications Networks
Monday, September 22, 8:30am – 12:30pm
Juliana 3 Conference Room

In this session, speakers from MathWorks, Mobile Experts, Vites GmbH, Rohde & Schwarz, and SIAE Microelettronica explore the rapid evolution of LEO satellite networks and their role in enabling 6G NTN. Topics will include terminal design, beamforming, antenna characterization, and system-level linearization. Industry experts will provide a comprehensive review of market trends, technical challenges, and ecosystem development.

Mitsubishi Electric – Building High-Fidelity HVAC Models with Dyad and Scientific Machine Learning

25 September 2025

November 13, 2025
11:00 AM (Eastern US)

Register

Overview

Join Christopher Laughman (Mitsubishi Electric Research Laboratories) and Avinash Subramanian (JuliaHub) for a webinar exploring how advanced simulation tools can transform HVAC system modeling.

Accurately estimating refrigerant mass in vapor-compression systems such as air conditioners and heat pumps, is essential for both performance and environmental assessment. Traditional methods are invasive, costly, or insufficiently precise.

In this webinar, Laughman and Subramanian will share how MERL used Dyad's (Formerly JuliaSim) ModelingToolkit-based workflows together with machine learning techniques to develop a non-invasive state estimation approach. By leveraging pressure and temperature data, their method can predict refrigerant mass and other hard-to-measure system variables with high accuracy, achieving errors of less than 2%.

What you'll learn:

- The limitations of traditional diagnostic methods in HVAC systems
- How Dyad enables high-fidelity modeling of vapor-compression cycles
- Combining physics-based models and machine learning for improved state estimation
- A MERL case study demonstrating <2% error in refrigerant mass prediction
- The potential of simulation-driven approaches to improve diagnostics, efficiency, and sustainability in HVAC

Register

Presenter: Christopher Laughman - Sr. Principal Research Staff, Mitsubishi Electric Research Laboratories
Christopher R. Laughman received the S.B. and M.Eng. degrees in electrical engineering and computer science and the Ph.D. degree in architecture from the Massachusetts Institute of Technology, Cambridge, MA, USA, in 1999, 2001, and 2008, respectively. He has been with Mitsubishi Electric Research Laboratories, Cambridge, since 2008, where he currently holds the position of a Senior Principal Research Scientist and is the Senior Team Leader of the Multiphysical Systems Team. His research interests include the modeling, simulation, control, and optimization of large-scale multiphysical systems, with an emphasis on multiphase thermofluid applications.

Presenter: Avinash Subramanian - Software Engineer, Simulation, Control, and Optimization, JuliaHub
Dr. Avinash Subramanian holds a PhD in Energy and Process Engineering from the Norwegian University of Science and Technology (NTNU). Before joining JuliaHub in January 2023, where he specializes in simulation, optimization, and control, he was a graduate researcher at the Process Systems Engineering Laboratory in the MIT Department of Chemical Engineering. Avinash also served as a Lecturer at NTNU from August to December 2022, where he co-taught a PhD course on Mixed-Integer and Nonconvex Optimization in collaboration with Professor

Paul Barton (MIT). His expertise bridges advanced optimization methods and their applications in process systems, energy, and industrial digital twin technologies.

Rockwell Automation Showcases End-to-End Autonomous Manufacturing at PACK EXPO 2025

23 September 2025

Rockwell Automation, Inc., the world's largest company dedicated to industrial automation and digital transformation, will showcase its end-to-end autonomous manufacturing solutions at PACK EXPO 2025 in Las Vegas Sept. 29 – Oct. 1.

Amidst shifting consumer demand and evolving regulations, Rockwell will demonstrate how it helps CPG manufacturers extend autonomy from raw-material movement via its OTTO autonomous mobile robots (AMRs) into the production process through integration across the Rockwell portfolio. This integrated solution delivers greater speed, efficiency, and resilience in end-to-end operations.

"Autonomous manufacturing is no longer a future concept, it's here today," said Steve Deitzer, VP Global Industry, Consumer Packaged Goods, at Rockwell Automation. "Every manufacturer is at a different point in their digital transformation, and we meet them where they are with practical, scalable solutions that unlock measurable value. At PACK EXPO we're showing how end-to-end autonomy can reshape operations and strengthen business outcomes today."

Attendees who visit booths SL-13028 and SL-13022 can see interactive demonstrations across the plant lifecycle.

- **Digital twins:** Emulate3D digital twin technologies enable manufacturers to virtually design, test, and commission equipment to reduce risk and timelines.
- **DataReady smart machines:** Pre-integrated with Logix controllers, FactoryTalk Optix and smart object data models, DataReady machines enable plug-and-play deployment, consistent data flows, and real-time insights for AI-driven optimization.
- **Material staging:** Plex Manufacturing Execution System directs OTTO AMRs to automate material staging and delivery while digitally connecting people, processes, and equipment on the plant floor.
- **AI-driven optimization:** LogixAI and VisionAI pair real-time AI together to maximize throughput, quality and cost efficiency.

More than 50 Rockwell partners will also feature Rockwell-enabled solutions across the show floor. Additionally, Rockwell will present on the Innovation Stage three times during the week:

- Transform What's Possible with Digital Twins (Sept. 29,1:30 p.m.)
- Industrial AI – Practical Examples to Address Manufacturing Challenges (Sept. 30, 11:30 a.m.)
- Accelerate Your Digital Journey with DataReady Machines (Oct. 1, 10:30 a.m.)

Financial News

Accenture Reports Fourth-Quarter and Full-Year Fiscal 2025 Results

25 September 2025

Accenture reported financial results for the fourth quarter and full fiscal year ended August 31, 2025.

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Addnode Group Presents New Financial Targets

22 September 2025

Addnode Group announces new financial targets. These new targets are intended to clarify Addnode Group's growth opportunities, potential in regards of profitability, and ambition for capital structure. The new financial targets will be presented in further detail during the live-streamed Capital Markets Day, commencing at 1:00 p.m. CEST today. To facilitate historical comparison, pro forma figures for the period 2015–2024 for net sales, EBITA margin and distribution of net sales by own software, partner software and services are attached with this press release. This document will also be made available on Addnode Group's website.

The new targets are in line with Addnode Group's existing strategy for profitable and sustainable organic and acquisition-driven growth.

Addnode Group develops and provides solutions that digitalize society. There are extensive business opportunities within the scope of global trends such as digitalization, urbanization, AI, and sustainability. Based on these trends, and with sound risk-taking, Addnode Group acquires, develops and manages knowledge-leading companies that contribute to the digitalization of a better society.

The New Financial Targets

- **EBITA growth.** Average annual EBITA growth shall amount to at least 15 percent, which corresponds to a doubling of EBITA over five years. This target replaces the previous target of achieving an average annual net sales growth of at least ten percent.
- **EBITA margin.** The EBITA margin shall amount to at least 17 percent. This target replaces the previous target of reaching an EBITA margin of at least ten percent.
- **Leverage ratio.** Net debt shall not exceed 2.5x EBITDA. This is a new target, reflecting the Group's ambition regarding its capital structure.
- **Dividend policy:** The dividend policy remains unchanged. 30–50 percent of the Group's profit after tax shall be distributed to the shareholders, providing its net cash position is sufficient to operate and develop its business.

"I am pleased to present Addnode Group's new financial targets today. They confirm our existing strategy, reflect a higher level of ambition in terms of growth and profitability, and clarify our objectives regarding capital structure. We aim to achieve these new targets by

focusing on business development, improving internal efficiency, and continuing to execute value-creating acquisitions," says Johan Andersson, CEO and President of Addnode Group.

Pro forma for the years 2015 – 2024

Financial tables with pro forma figures for net sales and EBITA margin for the period 2015–2024 and a distribution of net sales by own software, partner software and services are attached to this press release and will also be published together with all Capital Markets Day materials at 1:00 p.m. CEST at https://www.addnodegroup.com/sv/report/kapitalmarknadsdag2025/.

In 2024, a significant portion of sales of partner software, primarily within the division Design Management, began to be reported under an agency model. This made comparisons with previous periods more difficult, as both net sales and purchases of goods and services decreased, while gross profit and EBITA remained unchanged. The pro forma adjusts for these differences and presents historical financial figures as if the new transaction model and the reclassification of third-party agreements had been in effect since January 1, 2015.

To increase transparency and understanding of Addnode Group, starting with the interim report for the third quarter of 2025, net sales will be reported broken down by own software, partner software, and services. This disclosure will be made both for Group total and for each division. In connection with this, a historical pro forma of this net sales breakdown for the years 2015–2024, as well as the actual figures for Q1 and Q2 2025, will also be published.

Live webcast of the Capital Markets Day

The new financial targets will be presented in more detail during Addnode Group's Capital Markets Day in Stockholm today. Those who have not previously registered to participate on site, are invited to follow the live webcast starting at 1:00 p.m. CEST. The webcast, presentations, and pro forma will be available at: https://www.addnodegroup.com/sv/report/kapitalmarknadsdag2025/.

Honeywell to Release Third Quarter Financial Results and Hold Its Investor Conference Call on Thursday, October 23

25 September 2025

Honeywell will issue its third quarter financial results before the opening of the Nasdaq Stock Market on Thursday, October 23. The company will also hold a conference call at 8:30 a.m. EDT.

Presentation Materials / Webcast Details

A real-time audio webcast of the presentation can be accessed at https://www.honeywell.com/investor, where related materials will be posted prior to the presentation and a replay of the webcast will be available for 30 days following the presentation.

Implementation Investments

ADMARES industrializes sustainable housing design and manufacturing with Siemens Xcelerator

22 September 2025

Siemens announced that ADMARES, a leader in industrialized housing, is using the Siemens Xcelerator open business platform to apply Siemens' most comprehensive digital twin, advanced manufacturing and automation technology to design, build and operate sustainable and affordable housing.

Founded in 2016, ADMARES is a technology company applying advanced manufacturing techniques to the construction industry to build affordable, smart, connected and sustainable homes. Using highly flexible and modularized design combined with a clean sheet, digital first, automated greenfield smart factory ADMARES is aiming to eliminate up to 75% of the CO_2 emissions associated with residential construction by generating 80% less material waste and producing at speeds that will revolutionize how the global housing crisis is solved by advancing the traditionally conservative construction industry.

"Siemens' technology has enabled us to make affordable homes a product, rather than a process reliant on construction labor - of which there is a global shortage," said Mikael Hedberg, CEO, ADMARES. "When homes become productized, industrialized and digitalized, we're able to fully automate the manufacturing process and deliver homes the world so desperately needs at the affordable cost, scale and speed it needs."

"The work that ADMARES is doing is a compelling example of how Siemens technology enables entirely new business models to emerge. Building on the Siemens Xcelerator portfolio, ADMARES has transformed housing from a traditional construction process into a scalable, digitalized product," said Eryn Devola, Head of Sustainability, Siemens Digital Industries. "Our digital twin, automation and manufacturing technologies have empowered them to industrialize homebuilding – cutting emissions, reducing waste, and accelerating delivery. This is the kind of industry reinvention Siemens Xcelerator was designed to make possible."

At the core of its development is the Siemens Xcelerator portfolio of industry software. ADMARES has used Siemens' Designcenter, Teamcenter and Simcenter software to design, validate and prove out its modularized housing designs. They create a comprehensive Digital Twin that accurately represents not only the final productized smart home but contains vital data about the manufacturing process that is used to develop and optimize its smart factory. This factory, powered by Siemens' Opcenter manufacturing execution software and automation hardware, will achieve a takt time of 22.5 minutes per building unit, allowing the production of complete 1,400 ft^2 home in 45 minutes, delivered with building software for real-time monitoring of energy, water and air quality, making them fully connected smart homes.

AMLI Residential Selects Planera to Transform Project Scheduling and Field Collaboration

23 September 2025

Planera, the leader in visual CPM-based construction scheduling, announced that AMLI Residential, a leading multifamily developer, general contractor, and property operator, has selected Planera to streamline scheduling and boost collaboration across its construction projects.

Challenge: Outdated, Siloed Scheduling Tools
Before adopting Planera, AMLI relied primarily on Microsoft Project to manage its scheduling processes. While effective for basic sequencing, the tool created silos, limited collaboration, and required cumbersome manual updates. Field teams often reverted to Excel to generate weekly three-week look-aheads, which meant lost time and duplication of effort.

AMLI needed a modern, cloud-based solution that could unify office and field teams, simplify adoption, and deliver real-time transparency across projects.

Solution: Deploying Planera on the Littleton Project
In early 2025, AMLI launched Planera on its 310-unit Littleton, Colorado development—a wrap-style community built around a precast garage, including podium retail and five stories of wood-framed residential units. The Littleton team, known for its tech-forward approach, embraced Planera as a new solution to project scheduling.

Key benefits quickly emerged:

- **Canvas-Style Scheduling** – Assistant Project Manager Jake Berg built a 2,000-line master schedule in significantly less time than it would have taken in Microsoft Project.
- **Automated Look-Aheads** – The platform's three-week look-ahead feature replaced manual Excel updates, streamlining subcontractor meetings and reducing confusion.
- **Filtering for Field Use** – By filtering schedules by trade, activity, or scope, field superintendents could focus only on the data relevant to their teams.
- **Premium Training** – Onboarding support accelerated adoption, smoothing the transition and building confidence among staff.

Results: Faster, More Transparent Scheduling
Since adopting Planera, AMLI has seen significant improvements in efficiency and collaboration:

- **Time Savings**: Schedules were built and maintained more quickly, freeing staff for higher-value tasks.
- **Transparency**: Centralized, cloud-based schedules improved visibility across project teams, from junior staff to senior superintendents.
- **Field Buy-In**: Even initially skeptical superintendents came to trust Planera as a viable replacement for legacy tools.

- **Standardization**: AMLI transitioned away from updating Microsoft Project in parallel, committing to Planera as its primary scheduling platform.

"Planera allowed us to build a detailed master schedule much faster than ever before," said **Jake Berg**, Assistant Project Manager at AMLI. "We moved quickly from skepticism to full buy-in—field teams loved the visibility, and our manual Excel processes became a thing of the past. "

Leadership Perspective
"Construction scheduling has long been seen as a back-office task, siloed away from the people who need it most," said Nitin Bhandari, CEO of Planera. "By making scheduling visual, collaborative, and cloud-based, Planera empowers both office and field teams to work from a single source of truth. In addition, with more effective scheduling, Planera is helping AMLI to avoid the increased costs and schedule delays that stem from schedule compression. We're excited to support AMLI in scaling this transformation across their portfolio."

Looking Ahead
Following the success of the Littleton work, AMLI plans to roll out Planera across additional projects in its regional markets. AMLI aims to establish Planera as a company-wide scheduling standard for both master and field schedules and will transition away from its long-time use of Microsoft Project.

Everbest Boosts Omnichannel Efficiency and Accelerates Global Expansion with Centric PLM and Centric Planning

22 September 2025

Centric Software® is thrilled to announce that the Singapore-based footwear and accessories company, Everbest has selected Centric PLM™ and Centric Planning™ to drive efficiency for global growth. Centric Software provides the most innovative enterprise solutions to plan, design, develop, source, buy, make, price, allocate, sell and replenish products such as fashion, outdoor, luxury, footwear, outdoor, home and related goods like cosmetics & personal care as well as multi-category retail to achieve strategic and operational digital transformation goals.

Founded in 1979, Everbest delivers timeless, high-quality footwear and accessories, including bags and belts for both women and men. Everbest sells its products online and in 150 physical stores in Southeast Asia, such as department stores, outlet malls and retail shops. The company also owns two additional children's footwear specialty brands, EVB and The Tracce.

To achieve ambitious international expansion goals, Everbest recognized the necessity of digital transformation to modernize product development and retail planning processes with cutting-edge technology. "Our teams in China, Singapore and Indonesia were grappling with the use of spreadsheets to manage product and planning data for 500 SKUs per year across multiple channels and categories," shares a representative from Everbest. "This manual process often led to human errors, missing information and inconsistencies. As our business grew, we needed a unified platform to enhance efficiency and decision-making."

After evaluating various technology partners, Centric emerged as the clear choice due to its comprehensive product suite and strong industry references. “Centric impressed us with their product roadmap, industry know-how and impressive clientele,” the representative adds. “We immediately saw how Centric PLM and Centric Planning could transform our business. The solutions are user-friendly and offer a level of detail and automation that excites us.”

With the successful implementation of Centric PLM, Everbest now benefits from a single source of truth for product data, enhancing collaboration and driving product innovation. “With Centric PLM, task delegation is clearer, freeing up time for teams to focus on value-added tasks that support our growth plans. The onboarding process will also be much smoother and intuitive,” the spokesperson explains.

The implementation process went smoothly thanks to Centric Software’s experienced team and clear methodology. ”We’re excited to utilize Centric PLM and look forward to seeing the full impact of these solutions on our operations,” the spokesperson noted.

Building on this foundation, Everbest is implementing Centric Planning to strengthen its omnichannel strategy through three solution modules:

- Merchandise Financial Planning (MFP) – to set financial targets and translate them into actionable sales, margin and inventory plans
- Assortment Strategy – to define the right product mix across markets and clusters
- Assortment Planning and Buying – to select and purchase the right assortments by channel and region

Everbest’s merchandising, buyers and regional operational managers will be able to turn huge volumes of data into clear and accurate patterns and forecasts and use advanced analytics to drastically improve decision-making. “With Centric Planning, we anticipate faster inventory turnover and increased revenue and margins as we consolidate and organize our planning activities more efficiently,” the representative concludes.

“We are delighted to partner with Everbest as they implement Centric Planning and Centric PLM to digitally transform their business,” says Fabrice Canonge, President of Centric Software. “Everbest has been a trusted brand in the Southeast Asia region for decades, and we look forward to working closely with them for future growth, from planning to product go-to-market through the deployment of Centric Software’s end-to-end solutions.”

Infosys Extends Strategic Collaboration with Sunrise to Accelerate IT Transformation and Power AI Future

23 September 2025

Infosys, a global leader in next-generation digital services and consulting, announced the expansion of its strategic long-term collaboration with Sunrise, Switzerland's leading challenger, with a strong number two position in the Swiss telecommunications market, to accelerate its IT transformation. Infosys will support Sunrise in fostering a modern, agile, and secure technology foundation to drive innovation and to continue securing its future readiness. The collaboration

highlights the shared commitment of Infosys and Sunrise to customer-centric innovation through cutting-edge technology solutions, with a strong focus on IT transformation, data security, operational agility, and future AI integration.

Infosys has been an instrumental partner in streamlining Sunrise's IT landscape providing comprehensive end-to-end IT services, from design and development to testing, deployment, and operations. This extensive undertaking included successfully consolidating multiple vendors into a unified portfolio and seamlessly transitioning a variety of applications. These efforts, driven by the close collaboration and strong cultural alignment between Infosys and Sunrise teams, are enabling an even more scalable and secure technology environment crucial for advancing Sunrise's IT transformation and laying the groundwork for future AI-enabled efforts.

Infosys will leverage its expertise in AI, analytics, and data along with elements of Infosys Topaz, an AI-first offering using generative AI technologies, to support Sunrise in its efforts to position itself as an AI-powered organization. This will help Sunrise unlock new business value by delivering enhanced speed, efficiency, and quality in operations through data-driven insights, and intelligent automation. It will also deliver tangible improvements for customers through further enhanced service reliability, faster time-to-market for new offerings, and personalized digital experiences.

Anna Maria Blengino, CIO, Sunrise, said, " Through our strategic collaboration with Infosys, we are consolidating our technology landscape and infusing it with AI, putting enhanced customer experience at the heart of this transition. The Sunrise and Infosys teams are working side by side with a true one-team mindset to design and deliver platforms that are more agile, predictive, and scalable."

Upendra Kohli, Executive Vice President – Communication, Media and Technology (Americas & Europe), Infosys, said, "Our expanded collaboration with Sunrise underscores a shared vision for the telco of the future. By infusing advanced intelligence across their operations, Infosys is supporting Sunrise in its efforts to continuously innovate, and deliver unparalleled experiences for their customers, all while upholding the highest standards of data security and integrity. This collaboration is a testament to our commitment to helping clients become AI-powered enterprises and demonstrates how trust and operational excellence can deliver real business value."

Merck and Siemens deepen strategic partnership to accelerate AI and data-driven drug discovery and development

23 September 2025

Merck and Siemens have signed a new Memorandum of Understanding (MoU), extending their strategic partnership to accelerate digital transformation in the life science industry by connecting digital and physical products. The agreement focuses on delivering integrated software solutions, systems and consumables that harness automation, data and AI to connect drug discovery, development, and manufacturing. This agreement marks the first joint use of technology acquired by Siemens as part of the acquisition of Dotmatics that was completed in July 2025.

"Through this collaboration with Siemens, we are opening new possibilities for scientists to move faster from an idea in the lab to a therapy for patients," said Jean-Charles Wirth, Member of the Executive Board and CEO Life Science, Merck. "By combining our strengths, we aim to change how science advances, unlocking new ways to accelerate scientific progress."

"We are partnering with Merck to give scientists around the world the instruments to speed up the development of life-saving medication", said Cedrik Neike, Member of the Managing Board at Siemens AG and CEO of Siemens Digital Industries. "Every few years the cost for developing a new drug is doubling. Data, AI and digitalization are key to break this paradigm. We are connecting every step of drug development through a digital backbone – so that data flows seamlessly, insights emerge faster, and medication reaches the patients faster."

The collaboration will focus on digital-first solutions that close workflow gaps in drug discovery and biomanufacturing by integrating Merck's software-as-a-service (SaaS) products with Siemens' digital ecosystem. Initial pilot projects include making Merck's AI tools and digital applications available in Luma, Siemens' Scientific Intelligence Platform acquired as part of Dotmatics. This will give scientists a single environment that links product ordering with immediate access to the digital tools and insights they need to make faster, data-driven decisions.

Building on these projects, Siemens and Merck will pursue additional joint projects and explore deeper integration over time. These initiatives include co-developing smarter data management tools and intuitive interfaces that make advanced processes easier for scientists to use. The partnership is also evaluating digital marketplaces that would give customers streamlined access to complementary technologies and services.

Together, Merck and Siemens see digital innovation as central to the future of life sciences. This partnership is designed to set a new standard for digital transformation, giving scientists and manufacturers the tools to deliver breakthroughs faster. It also builds on earlier MoUs between the two companies in smart manufacturing, reflecting a shared commitment to advancing innovation across the industry.

One of the world's largest commercial vehicle manufacturers, headquartered in Sweden, selects HCLTech for AI-powered digital foundation services, renewing & expanding on original agreement

23 September 2025

HCLTech, a leading global technology company, and one of the world's leading manufacturers of trucks, buses, construction equipment, marine and industrial engines and comprehensive transport solutions, headquartered in Gothenburg, Sweden, announced that they have renewed their long-standing digital transformation agreement with an expanded scope of services.

Under a new multi-year contract, HCLTech will enhance and modernize the Gothenburg-based manufacturer's IT infrastructure and transform its digital foundation services. By leveraging its proprietary GenAI-led service transformation platform, AI Force, HCLTech will deliver platform-

based managed services, hyper automation and full-stack observability. The AI-powered solutions will enable one-click provisioning of IT services and will help optimize operational efficiency and enhance the employee and customer experience. HCLTech's solutions will accelerate the client's sustainability goals by advancing responsible and efficient IT practices.

"We are delighted to be a trusted digital transformation partner and contribute to the client's growth strategy. We look forward to leveraging our full-stack technology portfolio to build a future-ready digital foundation," said Jagadeshwar Gattu, President, Digital Foundation Services, HCLTech.

"We are proud to continue being a part of the client's growth journey. This renewal and expanded scope reflect the strong foundation we've built together over the years. The expansion of this strategic agreement further reinforces HCLTech's leadership in the global automotive vertical, which is amongst the company's key growth areas," added Pankaj Tagra, Corporate Vice President, HCLTech.

Wild Foods Accelerates International Expansion with Centric PLM Automation

25 September 2025

Centric Software® is proud to share the success story of Wild Foods, a fast-growing Chilean healthy food brand that has embraced digital transformation to fuel international expansion. Centric Software provides the most innovative enterprise solutions to plan, formulate, develop, procure, manufacture and sell consumer goods products in food & beverage, grocery, fashion and multi-category retail to achieve strategic and operational digital transformation goals.

Wild Foods has been dedicated to reshaping the food industry since its inception by offering real, healthy food. Currently boasting a team of 120 employees, with offices in Chile and Mexico, products are also sold in Colombia, Brazil, Peru and the United States. The company is dedicated to inspiring healthier lifestyles and promoting transparency in its offerings. The mission is clear: to deliver high-quality, reliable alternatives to conventional, mass-market food products.

Rapid company growth brought on significant challenges. Wild Foods struggled with inconsistent nutritional data management, scaling internationally and labor-intensive manual tasks prone to errors. These hurdles were especially critical given Wild's commitment to accuracy and compliance. "As a health-focused food company, our consumers are very knowledgeable. They carefully review nutrition labels and what they consume, trusting that the information is accurate," explains Matías Arriagada Juliá, Lead Systems Engineer at Wild Foods.

To tackle these issues, Wild Foods chose Centric PLM™ to be a powerful catalyst for growth. The results are remarkable: faster time to market, centralized and accessible data, improved traceability and compliance as well as the automation of time-consuming nutritional calculations. "What used to take 15 minutes to do, now takes one click; the calculations are done instantly," shares Amelia Muzzo Araus, Food Product Engineer at Wild Foods. This automation not only saves time, but eliminates human error, ensuring accuracy. Since implementing Centric PLM, Wild Foods has achieved flawless compliance and avoided product recalls, further strengthening consumer trust.

Yamaha Motor Accelerates Innovation with Informatica's AI-Powered Master Data Management for Trusted Data and Insights

23 September 2025

Informatica, a leader in enterprise AI-powered cloud data management, announced that Yamaha Motor Co., Ltd., a global leader in transportation equipment manufacturing, has chosen to implement Informatica's AI-powered Master Data Management (MDM) solution as part of the customer's digital transformation strategy.

Yamaha Motor was faced with challenges of managing extensive and complex data and siloed systems across its manufacturing and business operations in different global locations. Furthermore, Yamaha Motor's global ERP systems required the unification of data standards and data harmonization from instances and contents which differ from region to region, and the inability to share the same master data to each group company's ERP systems and business systems further hindered operational efficiency of the businesses.

To overcome the challenges, Yamaha Motor is implementing Informatica's industry-leading multidomain MDM SaaS solution, powered by Informatica's CLAIRE® AI engine, to streamline, centralize, and automate cross-domain and cross-departmental data assets for a comprehensive, contextualized 360-degree view. This implementation helps enable the organization to boost productivity, accelerate data discovery, and deliver high-quality, consistent and accurate data for trusted insights.

"With the implementation of Informatica's MDM, Yamaha Motor is creating an interface platform that seamlessly connects each region's ERP systems with our proprietary scratch systems, enabling trusted master data management on a global scale," said Toyoto Ono, Chief General Manager, IT Center at Yamaha Motor Co., Ltd. "This platform enhances decision-making, forecasting and reporting processes, while driving productivity improvements and cost efficiencies through the effective ERP system deployment and maintenance. It represents a vital step in establishing a robust foundation to support our sustainable business growth and strengthen organizational resilience."

Taito Kozawa, Country Manager and Vice President of Informatica Japan says, "We are very pleased to partner with Yamaha Motor as they modernize their global data management infrastructure. Together, we are supporting their goal to strengthen data-driven decision-making and accelerate AI and digital transformation. As many organizations in Japan pursue similar initiatives, we remain committed to working with our customers to help them realize meaningful business values through our AI-powered platform and capabilities."

Product News

Alphawave Semi Taped-Out Industry Leading 64Gbps UCIe™ IP on TSMC 3nm for the IP Ecosystem, Unleashing Next Generation of AI Chiplet Connectivity

24 September 2025

Alphawave Semi, a global leader in high-speed connectivity and compute silicon for the world's technology infrastructure, announced the successful tapeout of the industry's leading 64 Gbps UCIe™ die-to-die (D2D) IP subsystem on TSMC's 3nm process technology. Building on its 36 Gbps Gen2 silicon success, this third-generation subsystem delivers a major advancement in performance and shoreline bandwidth density for the IP Ecosystem. With 64 Gbps per-lane uni-directional data rates, it enables the next generation of chiplet-based architectures for AI, XPUs, and data center systems, providing power-efficient, reliable multi-die SoC integration and seamless interoperability across the chiplet ecosystem.

As the first 64 Gbps UCIe™ IP subsystem implemented on TSMC's 3nm process, this achievement positions Alphawave Semi as a leader in UCIe die-to-die connectivity technology. With enhanced 64 Gbps UCIe performance and reduced power consumption, the solution enables new applications, including optical connectivity for Co-Packaged Optics (CPO), which are essential for scalable systems and environments requiring high lane count radix. Furthermore, it expands D2D interconnect capabilities, supporting a custom memory interface that delivers very low power and latency with a unique form factor, offering eight times greater bandwidth density compared to conventional memory interfaces.

Built on a silicon-proven architecture spanning multiple process nodes, Alphawave 64 Gbps UCIe delivers twice the bandwidth density of previous UCIe, achieving up to 3.6 Tbps/mm shoreline bandwidth in the Standard Package and more than 21Tbps/mm in the Advanced Package. This subsystem uses advanced architecture to enhance performance and reliability. With Alphawave's proven D2D technology and adaptable firmware, customers can quickly develop and deploy chiplet-based solutions for changing market demands.

Alphawave offers an integrated D2D subsystem that supports protocols such as AXI-4, AXI-S, CXS, CHI, and CHI C2C, empowering flexible chiplet-based systems and providing a reference architecture for faster development. The 64 Gbps UCIe IP is fully compliant with UCIe 3.0 (released in August 2025). It includes robust test and debug features—iJTAG, BIST, DFT, Known Good Die (KGD), and live per-lane health monitoring—to ease customer integration and enhance reliability.

"The industry's first tapeout of our Gen3 UCIe™ IP at 64 Gbps on TSMC's N3P process marks a significant leap forward in die-to-die connectivity," said Mohit Gupta, Executive Vice President & General Manager, Alphawave Semi. "Building on our success on the silicon for 36 Gbps UCIe IP at N3P, this achievement positions Alphawave Semi at the forefront of delivering ultra-high-performance and shoreline bandwidth density compared to prior generations. Just as importantly, it strengthens our broader AI platform—ensuring our suite of IP subsystems now delivers higher performance and efficiency than ever before on the 3nm process to meet the critical bandwidth demands of scalable AI compute."

"Our collaboration with Alphawave Semi reflects our shared commitment to advancing high-performance, energy-efficient computing through leading design solutions on TSMC's 3nm technology," said *Aveek Sarkar, Director of Ecosystem and Alliance Management Division* at TSMC. "This achievement demonstrates how close collaboration with our Open Innovation

Platform® (OIP) partners accelerates the delivery of advanced interface IP and custom silicon solutions to meet the rapidly growing demands of AI and cloud infrastructure."

This tape out marks a defining milestone for Alphawave Semi's AI platform and chiplet reference architecture, establishing the foundation for the next generation of chiplet connectivity across hyperscaler, data center, and AI applications. The rapid progression from 36 Gbps to 64 Gbps on TSMC's 3nm process reflects our leadership in advancing open, scalable chiplet ecosystems and our commitment to shaping the future of ultra-high-performance connectivity.

Aurigo Software Expands Autodesk Integration to Offer Integrated Capital Planning to Facility Owner-Operators

23 September 2025

Aurigo Software, North America's leading capital planning software provider, announced a fully integrated solution that brings together Aurigo's capital planning product with Autodesk Construction Cloud®, a comprehensive construction management solution that connects workflows, teams, and data across every stage of a project, from design and planning through building and operations. The new integration enables Autodesk's facility owner and operator customers to seamlessly connect long-range strategy and funding decisions with downstream project execution.

Project teams can now integrate Projects, Budgets, Commitments, Change Orders, and Expenses between Autodesk® Build Cost Management and Aurigo Primus Plan for planned vs. actual performance updates.

Recent data from the U.S. Census Bureau indicate that construction across multiple sectors of the economy is on the rise, including data centers, manufacturing, and healthcare. Planning and finance teams need modern tools to address the complexity of these capital programs. Capital owners who are already utilizing Autodesk's best-in-class construction solutions will now be able to collect, prioritize, program, and track performance of their projects from their very inception, before any asset is designed or built. By moving the management of capital programs upstream, risks can be identified early, and returns on investments can be calculated more easily.

"With the integration, we are creating a single, connected loop for capital assets, starting in planning and moving to design, construction, and maintenance," said Balaji Sreenivasan, CEO and founder of Aurigo Software. "By connecting Aurigo's capital planning expertise to the breadth of execution offered by Autodesk Construction Cloud, every investment decision carries through to delivery, allowing owner-operators to make the right decisions faster."

Today, Aurigo manages more than $450 billion in capital programs across 40,000 projects, making it an ideal planning solution for North America's largest capital owners. Building on this expertise, the company introduced Aurigo Primus, the industry's first AI-powered capital planning system purpose-built for facility owners.

With Primus, users can define project charters, model funding scenarios, and forecast outcomes. The platform goes beyond traditional approaches to include predictive analytics and generative modeling to enable smarter portfolio optimization, risk assessment, and cost control. When paired with Autodesk Construction Cloud, owners can publish approved projects and budgets into downstream workflows, while instantly synchronizing commitments and actuals from the field to understand their portfolio performance in real time.

"Autodesk and Aurigo share a commitment to helping owners deliver smarter, more sustainable assets," said Sidharth Haksar, vice president, construction strategy & industry partnerships at Autodesk. "By integrating Aurigo's capital planning platform with Autodesk Construction Cloud, we are connecting the why, what, and how of every program, helping our customers deliver with greater accountability and transparency at every stage of the lifecycle."

Cadence Partners with TSMC to Power Next-Generation Innovations Using AI Flows and IP for TSMC Advanced Nodes and 3DFabric

24 September 2025

Cadence announced major advancements in chip design automation and IP, driven by its long-standing relationship with TSMC to develop advanced design infrastructure and accelerate time to market, for AI and HPC customer applications. Cadence and TSMC have collaborated closely across the spectrum from AI-driven EDA to 3D-ICs to IP and photonics, enabling the world's most advanced semiconductors.

Cadence and TSMC have worked together on design infrastructure for advanced process nodes, including TSMC N3, N2 and A16™, using Cadence® Innovus™ Implementation System, Quantus™ Extraction Solution and Quantus Field Solver, Tempus™ Timing Solution and ECO Option, Pegasus™ Verification System, Liberate™ Characterization Portfolio, Voltus™ IC Power Integrity Solution, Genus™ Synthesis Solution, Virtuoso® Studio and Spectre® Simulation Platform. Cadence AI design flows for chip and 3D-IC are now available for TSMC's advanced N3, N2 and A16™ process technologies, as well as for new features in TSMC 3DFabric. Additionally, Cadence is collaborating with TSMC on EDA flow development for TSMC's A14 process, with its first PDK to be released later this year. Further, several new Cadence IP are now silicon-proven and available for TSMC N3P.

"Cadence and TSMC remain committed to speeding up and improving the design process for advanced silicon for our customers," said Chin-Chi Teng, senior vice president and general manager of the Digital and Signoff Group at Cadence. "We're helping designers develop the next generation of AI and HPC by supporting TSMC's leading technologies with AI features, IP and beyond."

"TSMC, together with our Open Innovation Platform® (OIP) partners like Cadence, is addressing some of the most intricate challenges in semiconductor development to drive higher performance and energy efficiency in AI systems," said Aveek Sarkar, director of the Ecosystem and Alliance Management Division at TSMC. "Our enduring partnership continues to empower

our mutual customers to accelerate their journey to silicon while driving the rapid proliferation of AI."

AI-Driven Chip Design Solutions for TSMC Advanced Process Technologies

Cadence and TSMC have partnered on AI-driven design solutions for joint customers, enabling chip development with optimal power, performance and area (PPA) in TSMC N2. TSMC has enabled Cadence JedAI Solution, Cadence Cerebrus® Intelligent Chip Explorer's AI-driven implementation technology and productivity features powered by Innovus+ AI Assistant within Cadence's digital full flow. Additionally, TSMC has validated new AI-driven features, such as automated design rule check (DRC) violation fixing assistance, enabling faster design closure and greater efficiency in the development of AI chips using TSMC N2.

Boosting Productivity for 3D-IC Designs

The Cadence 3D-IC solutions provide comprehensive support for TSMC's advanced packaging and die stacking configurations offered by 3DFabric. The latest innovations include automation features for bump connections, physical implementation and analysis for multiple chiplets and smart alignment marker insertion. The AI-driven application of Cadence's Clarity™ 3D Solver and Sigrity™ X Platform with Optimality™ Intelligent System Explorer enables and automates the 3Dblox-based system-level SI/PI analysis and optimization. Customers using TSMC Compact Universal Photonic Engine (TSMC-COUPE™) multi-wavelength reference flow can utilize Virtuoso Studio with the Celsius™ Thermal Solver, along with productivity enhancements developed by TSMC and Cadence, including effective thermal simulation techniques for lowering the risk of declining electrical and photonic performance.

Leading-Edge IP for TSMC N3P

Cadence continues to drive innovation in AI and HPC by delivering silicon-proven, cutting-edge IP solutions on TSMC's advanced processes, including N3P process technology, and helps customers build faster, more efficient and scalable systems. Cadence IP enables AI infrastructure by accommodating the memory and interconnect bandwidth capacity of next-generation AI LLMs, agentic AI and other compute-heavy workloads. New Cadence IP on TSMC N3P process technology includes the first HBM4 IP at N3P, high-speed memory interfaces like LPDDR6/5X at 14.4G and versatile DDR5 12.8G MRDIMM Gen2 IP that provide a wide range of options for customers as they address the memory-wall problem limiting AI compute systems. Cadence also leads in connectivity with PCI Express® (PCIe®) 7.0 IP—achieving a 128GT/s, 224G SerDes for AI infrastructure—and the first eUSB2V2 and Universal Chiplet Interconnect™ (UCIe™) 32G IP that support emerging AI PC and chiplet ecosystems, demonstrating its commitment to driving energy-efficient, scalable solutions for future workloads.

Together, Cadence, TSMC and the OIP Ecosystem are empowering the AI supercycle by streamlining the customer journey from design to silicon and enabling customers to enhance design performance and energy efficiency.

Chaos Redefines AI Imagery for Furniture with the Launch of Cylindo Quickshot

18 September 2025

Chaos announces Cylindo Quickshot, an AI solution that enables furniture retailers and manufacturers to generate on-brand lifestyle imagery in seconds, without the common frustrations seen in generic AI tools, such as image distortion, off-scale products, and mismatched props. Cylindo is the visual commerce platform for product visualization, used by leading furniture brands to create, manage, and distribute photorealistic content at scale.

AI imagery has become one of the hottest trends of 2025, but when it comes to furniture, most tools fail. Quickshot is built on Cylindo's 3D master assets to preserve true scale and proportions while giving teams direct control over composition, lighting, and props so results are ready for product detail pages (PDPs) and campaigns. Quickshot is backed by the Cylindo visual commerce platform, including the Content API and Curator, so images move from creation to PDPs and campaigns in minutes with consistent delivery across channels. Data from leading furniture brands shows that stronger PDPs and immersive online experiences can lift conversion by up to 36% and increase average order value by 71%, with lifestyle imagery playing a key role.

Current performance shows **one in six Quickshot AI images is immediately usable** under Cylindo's quality guidelines, already ahead of typical results from generic AI tools. Results improve with use, giving brands even more efficiency as they scale content production.

"Quickshot is not another AI background tool. It merges AI speed with 3D accuracy, guarantees scale and proportions, gives teams control over layout and styling, and plugs directly into distribution so visuals move from creation to campaigns in minutes," said Jostein Pedersen, Vice President of Product for Cylindo. "With photorealistic images generated in seconds, brands can accelerate test cycles and launches, create more relevant experiences across channels, and secure a competitive edge."

Early customers are seeing the impact on content velocity and team focus. "Quickshot makes it straightforward to create lifestyle imagery that supports our goals," said Søren Hansen, E-commerce Manager of MAKE Nordic. "Faster visuals mean quicker campaigns, and the ability to scale content without extra cost helps us focus on engaging shoppers and growing the business."

Why Quickshot is different

- Correct scale, every time. Built on Cylindo 3D master assets so products shown as exact digital replicas, not AI guesses.
- Creative control, not compromise. Direct control of composition, lighting, props, and scene to stay on brand.
- Speed that ships. Generate photorealistic lifestyle images in seconds and iterate fast without 3D expertise.

- From creation to channels. Seamless distribution via the Cylindo Content API and Curator to push assets live across PDPs and campaigns.

Key capabilities

- 1.5K native resolution lifestyle imagery optimized for web.
- Prompt or reference-image guidance applied to a user-staged 3D scene for on-brief results.
- AI-based post-processing to add or replace props and fix minor artifacts in seconds.
- Seamless publishing through the Cylindo Content API and Curator.

Cyncly expands FeneVision WEB CONNECT with Leap SalesPro integration for faster in-home window and door sales

24 September 2025

Cyncly, the world's leading global provider of software and content solutions that help make amazing spaces for living, announced a partnership with Leap SalesPro, a leading in-home sales platform for remodelers and home improvement contractors. Manufacturers publishing products to FeneVision WEB can now sell products directly through distributors using Leap SalesPro. Cyncly will continue expanding its partner program, enabling manufacturers to publish once and distribute across multiple selling channels with full control and consistency.

FeneVision WEB CONNECT, available as an add-on to FeneVision WEB, gives manufacturers the power to integrate their product catalogs directly with leading selling tools. By making accurate product data and pricing available inside the dealer's preferred in-home selling solution, WEB CONNECT:

- Accelerates estimates with precise, up-to-date product configurations.
- Improves customer relationships by simplifying how dealers and contractors access catalogs without leaving their selling tools.
- Increases shop floor efficiency by reducing errors and minimizing manual data entry between quote, sale and production.

"Our goal is to make it easier and faster for manufacturers to get their products into more homes," said Don Busiek, General Manager of Cyncly Windows, Doors and Glass solutions. "Adding Leap as a partner represents an important step forward for manufacturers and their dealer networks. By expanding the number of in-home selling solutions connected to our platform, we're giving manufacturers a seamless way to sell more effectively and with greater accuracy."

"At Leap, we're committed to giving dealers the tools they need to sell with confidence," said Kevin Geiger, Senior Vice President of Partnerships at Leap. "This integration with Cyncly's WEB CONNECT ensures that dealers can quickly generate accurate quotes, present professional proposals, and close more business — all with real-time manufacturer data."

The partnership with Leap builds on Cyncly's growing ecosystem of distributor partners, enabling distributors to bring the product catalog and pricing capabilities of FeneVision directly to their users. Cyncly is continuing to expand WEB CONNECT through integration with additional sales tools, further strengthening its position as the software partner of choice for the window, door, and glass industry.

Cyncly launches On-Demand Content in Worksheet to streamline catalog updates for dealers and manufacturers

25 September 2025

Cyncly, the world's leading global provider of software and content solutions that help make amazing spaces for living, announced the release of On-Demand Content in Worksheet, a major update that simplifies catalog updates for both manufacturers and dealers. With this update, Worksheet users can now access catalog updates directly within their workflow—faster, smarter, and without interruptions.

"The Cyncly Worksheet 2025 On-Demand Software Updates and Catalog Updates are a major step forward in efficiency and accuracy for both manufacturers and designers," said Sarah Girard, Cyncly Commercial Product Manager. "We hear from our customers all the time that real-time catalog information is essential to their business. This new system gives manufacturers more speed, control, and flexibility than ever before, while making catalog updates seamless and stress-free for our dealers."

This release marks a significant step in modernizing the Worksheet experience by eliminating the need for manual downloads or separate tools like the Content Downloader. Instead, updates are fully integrated into the platform, enabling greater efficiency across the supply chain.

For dealers, users can choose between automatic or manual catalog checks. Users receive notifications when updates are available, and a direct connection to the Catalog Center inside Worksheet.

For manufacturers, this means faster catalog publishing and hot fixes, the ability to schedule exact release dates, and the end of downtime for catalog availability.

Worksheet is powerful, easy-to-use furniture specification software for office designers, enabling them to create accurate, professional quotes, manage pricing, and streamline project workflows. Worksheet enables users to quickly build proposals, compare options, and manage updates across multiple projects. The solution reduces quoting errors, improves speed to market, and provides a consistent experience for both sales teams and customers.

Users are encouraged to update their version of Worksheet before December 31, 2025 to receive ongoing catalog updates and support.

Emerson Introduces AI-Enabled Guidance to Support Industrial Resilience

23 September 2025

Emerson, an industrial technology leader delivering advanced automation solutions, has introduced Guardian™ Virtual Advisor, an AI-powered software solution to support end-to-end lifecycle management. Emerson's Guardian Virtual Advisor combines AI with deep domain expertise to help customers rapidly evaluate and enhance the performance of their automation systems, driving smarter decisions and operational excellence.

Lifecycle services provide a comprehensive approach for industrial customers to support and maintain operations throughout the entire lifecycle of a plant – helping them maximize uptime, address operational inefficiencies and protect their automation investments. Frost & Sullivan estimates the industrial space has more than $1 trillion in operational losses globally, driving greater demand for lifecycle services.

For over two decades, Emerson's Guardian Digital Platform has accumulated a vast repository of troubleshooting information – but searching articles and reference documents is a manual approach that slows down quick responses to developing issues like performing system maintenance or managing security updates or new software releases. Guardian Virtual Advisor is an intuitive, AI-powered application where users can enter natural language questions and receive an easy-to-understand answer and a link to the appropriate reference documents.

"When a user is in the middle of a task, they don't want to read through thousands of knowledge base articles; they want the answer as soon as possible," said Nina Golder, vice president of Emerson's Guardian software and solutions. "Guardian Virtual Advisor quickly provides the direct answer to questions in conversational language, and delivers the referenced product information or system-specific hotfixes, saving valuable time and energy so teams can keep systems running at peak performance."

Currently available today to manage DeltaV™ distributed control systems, Guardian Virtual Advisor will be extended to include Emerson's other automation platforms, such as AMS and Ovation™. The Guardian Digital Platform and Guardian Virtual Advisor will play an increasingly critical role in accelerating time-to-market, reducing costs, maximizing asset utilization and eliminating operational risks.

Guardian Virtual Advisor is available to subscribers of Emerson's product support through the Guardian Digital Platform.

ENCY Hyper for Robot Programming Unifies Offline Precision with Real-Time Control

22 September 2025

ENCY Software announced the market release of **ENCY Hyper**, the company's next-generation system for programming and simulating industrial robots and auxiliary equipment. ENCY Hyper blends the flexibility of offline programming with the responsiveness of real-time methods in a streamlined workflow designed for tablets and industrial PCs. The product will be officially presented at **EMO Hannover 2025**.

What ENCY Hyper is — at a glance

- **Next-generation programming & simulation**. A hybrid system for industrial robots and auxiliary equipment that merges offline precision with real-time responsiveness in a touch-optimized workflow.
- **Key capabilities**: real-time robot and sensor feedback; AI-powered auxiliary tools; built-in collision avoidance; complete digital twin of the robotic cell; easy multi-brand robot calibration and programming from a single interface.
- **Use it solo or together with ENCY Robot**. ENCY Hyper can be used independently for pick-and-place, palletizing, packaging, or assembly — or seamlessly paired with ENCY Robot for advanced applications like milling, welding, spraying, or grinding.
- **Unified, interactive environment**. The system communicates with the robot in real time, enabling immediate execution, testing, and adjustment of robot motion. Control logic and motion can be fine-tuned interactively and responsively, giving integrators and engineers full control from design to deployment.

What's broken today — and why it slows you down

Online (teach-pendant) programming — intuitive, but limited. It's quick for tweaks and runs directly on the controller, yet it doesn't scale to complex paths, depends on operator skill and visual judgment, lacks full-cell simulation, and forces all testing onto the real cell—raising risk and downtime.

Offline (CAM + simulation) — powerful, but brittle at hand-off. You can generate precise paths and verify them in a digital twin, but small real-world deviations (mounting offsets, gripper wear, tilted fixtures) create a gap between simulation and reality. And even a simple on-cell change forces an engineer to go back to the office, regenerate the program, copy it to a USB stick or network share, walk it to the robot, load and test it — and then repeat that loop for every small correction.

How ENCY Hyper eliminates the trade-off

To solve those issues, ENCY Hyper unifies a complete digital twin and CAM-level accuracy with live robot communication in one hybrid, touch-optimized environment—so you keep the strengths of both offline and online methods without their downsides.

Addresses online (teach-pendant) limitations

- **Scale without point-by-point teaching**. Define what to pick and where to place; Hyper generates and executes motion in real time for routine tasks like pick-and-place, palletizing, packaging, or assembly.
- **See before you move**. Keep the responsiveness of online edits while gaining simulation of the complete robotic cell, so you're not "testing blind" on production hardware.
- **Safer, faster debugging**. Stream commands to the controller, step through with live robot and sensor feedback, pause instantly, and resume safely.

Fixes offline (CAM + simulation) hand-off issues

- **Eliminates the office↔cell loop**. Instead of exporting, copying, and walking files back and forth, Hyper streams programs directly to the robot for immediate execution and on-the-spot adjustment.
- **Closes the twin-to-reality gap**. Use point-and-confirm calibration: show a few real pick/place points; Hyper updates the digital twin and automatically recalculates the rest.
- **Built-in collision avoidance**. As you adjust on the cell, Hyper continuously checks and generates obstacle-aware paths to keep edits safe.
- **Multi-brand, one interface**. Calibrate and program robots from different vendors through a single UI; add drivers to expand coverage without retooling your process.
- **Right-sized effort for quick jobs**. Skip heavyweight CAM rebuilds when you only need small changes; make them directly with immediate, real-time feedback.

Where ENCY Hyper Delivers — From Simple to Complex

ENCY Hyper's hybrid workflow applies from straightforward cells to advanced toolpaths, combining digital-twin confidence with live, on-cell execution. Examples below are illustrative, not exhaustive.

Simple operations

- **Brownfield palletizing with drifting fixtures** (*6-axis robot on a 7th axis, palletizing/depalletizing*) — Stream programs to the controller, tweak layer patterns at the cell, and quickly recalibrate offsets from a few real pick/place points; collision checks help maintain clearances near posts and guards.
- **Kitting and light screwdriving** (*collaborative 6-axis cobot, assembly/screwdriving*) — Nudge targets on a tablet and stream updated moves in real time; I/O feedback confirms each step without point-by-point reteaching.

Advanced operations (with ENCY Robot)

Everything you can program in ENCY Robot can be run with ENCY Hyper. The advantage is where you make changes: at the robot, without a round-trip to the office. Operators and engineers can interactively adjust part locations, approaches and exits, batch size, tray/box destinations, step size, and number of passes right in Hyper. If you need to process a different part, you update the CAM project in ENCY Robot; for day-to-day production changes on the same part, you use Hyper.

- **Robot milling** (*6-axis robot, optional linear 7th axis; spindle*) — Programs are generated in ENCY Robot and tuned on the floor in Hyper (approach/exit edits, feeds, local adjustments).
- **Grinding/polishing/deburring** (*6-axis robot; abrasive/finishing tools*) — Generate toolpaths in ENCY Robot; in Hyper, adjust passes, step size, and approach/exit moves interactively next to the robot.

- **Coating/painting** (*6-axis robot + rotary table*) — Use ENCY Robot for path definition; in Hyper, refine process parameters like number of passes and start/stop timing at the cell.
- **Arc welding** (*6-axis robot + 2-axis positioner; GMAW/TIG*) — Define and simulate in ENCY Robot; at the cell, Hyper lets you adjust weld parameters such as weave step, pass length, and strategy without rebuilding the CAM project.

By removing the false choice between fast-but-risky online tweaks and precise-but-brittle offline workflows, ENCY Hyper accelerates commissioning, improves flexibility on short runs and changeovers, and reduces downtime. It's especially valuable for manufacturing and robotics engineers (one environment from design to deployment with easy last-mile corrections), shop-floor operators and technicians (safe, guided on-cell edits without point teaching), system integrators (shorter FAT/SAT cycles, fewer site revisits), and OEMs/machine builders (consistent multi-brand workflows and simpler field updates).

Latest Release of Hexagon's CT-scan Data Analysis Software Includes the 2025 iF-Award-Winning Porosity and Inclusion Analysis Tool

19 September 2025

In this month's release of version 2025.3 of its VG software, **Hexagon** has now incorporated the enhanced version of its powerful Porosity & Inclusion analysis (PIA) tool that won an **iF Award** earlier this year.

Many automotive, aerospace and other manufacturers who use CT-scan-data analysis for quality assurance are already frequent users of this tool. Now enhanced with AI, the PIA quickly pinpoints and identifies discrepancies—such as pores and inclusions deep within metal, plastic or composite parts, components or material samples—from early product development stages through final manufacturing.

"This is the first time our tool combines all previous methods into a single, powerful solution, from analysis to reporting," says Jan Gräser, Product Manager VG Product Line, Manufacturing Intelligence Division. "We've completely redesigned the user interface for this feature to make it easier for everyone—from beginners to experts—to employ the PIA to understand their results and conduct even the most complex analyses easily, accurately, and efficiently."

Key features in the Porosity & Inclusion Analysis:

- **Intuitive design**: All important settings are immediately visible and summarized at a glance, while advanced options are clearly accessible on separate tabs.
- **Efficient workflow**: Fewer clicks, more overview, maximum control. For the first time, all porosity/inclusion analysis procedures have been brought together in a single solution. This allows for direct access to the core functions and eliminates the need to switch between different dialogs, saving valuable time.
- **Easier navigation**: The new preview in the analysis dialog combines all key information and makes navigation easier thanks to the interactive minimap that shows the user's current position in the analysis window.

Other features in Hexagon's 2025.3 VG software release:

- **Multipart coordinate measurement.** This feature simplifies the handling of complex projects by allowing users to view, analyze, and edit measurement plans for multiple parts in one central location. The enhancement includes essential statistics for features directly in the feature list; interactive plotting of different values across all parts for individual features; and functions for directly editing, removing, and transferring features and geometry elements across all parts.
- **Create and modify dimensions directly in the 3D view (Image 3).** With the "Dimensioning" dialog open, create and adjust dimensioning features by dragging and dropping the measurement lines directly in the 3D view, allowing for easy placement in the correct direction and optimal visibility. Additionally, by holding down the "Alt" key, you can create projected dimensions on a preview plane. This enhancement ensures that all lines remain both visible and adjustable, even when located inside the material.
- **Improved deformation field capabilities for optical scans.** This significant enhancement is specifically designed for complex morphing of incomplete optical scans. Optical scans can often be challenging in deformation field computation, including issues such as missing parts because of scanner limitations and the need for precise matching, particularly in one-sided scanning scenarios. This improvement allows for more accurate and comprehensive handling of complex optically scanned parts, ensuring precise alignment and analysis even under challenging conditions.
- **Enhanced mesh import/export now supports GLB/GLTF, AMF, and 3MF file formats (Image 4).** This makes it easier to exchange 3D surface data with other applications. This allows users, for example, to directly import and use mesh data created for additive manufacturing and stored in AMF or 3MF formats as nominal reference data without the need to convert it to an intermediate format—or export colored meshes created from analysis results or extracted from volume objects in GLB format, which can be easily exchanged with other applications such as PowerPoint.

"Our goal with the redesigned Porosity & Inclusion Analysis feature, as well as others in version 2025.3, is to streamline the way our users work with our software, helping them make decisions about design and manufacturing parameters faster and more efficiently," says Dr. Daniela Handl, General Manager VG, Manufacturing Intelligence Division.

"These robust capabilities will improve workflows and elevate the non-destructive evaluation process for a wide variety of manufacturers who employ 3D CT scanning for quality assurance."

Siemens accelerates complex semiconductor design and test with Tessent IJTAG Pro

22 September 2025

Siemens Digital Industries Software announced Tessent™ IJTAG Pro software, which will transform IJTAG (IEEE 1687) input/output by enabling parallel operations of the traditionally serial operation and provide read and write access to custom hardware. The new software introduces high-bandwidth internal JTAG (IJTAG) and generic data streaming functionality to

help customers reduce test cost and time by accelerating data using the wide bus of Siemens' Tessent Streaming Scan Network (SSN) software.

The semiconductor industry is facing an unprecedented and accelerated evolution as transistor density expands across multiple dimensions. As semiconductor designs advance from 2D to 2.5D to full 3D IC architectures, design testing challenges have multiplied exponentially. The escalating test pattern counts, longer pattern application times, high ATE (Automatic Test Equipment) costs and limited number of test pins accessibility mean that optimizing existing infrastructure for test scaling is not just crucial but imperative for maintaining a competitive edge in the design process.

"In today's complex IC designs, test time optimization is a significant challenge. By utilizing Siemens' SSN architecture to convert traditional serial IJTAG operations into high-bandwidth parallel processes, Tessent IJTAG Pro not only accelerates test and reduces cost associated with test but also provides flexibility needed for revolutionizing test access to meet the industry's evolving needs," said Ankur Gupta, senior vice president and general manager, DDCP, Siemens Digital Industries Software. "As semiconductor design is scaling from simple 2D into full 3D IC architectures, test cost savings will be applicable in each chiplet as well as the entire 3D IC package."

"High-Bandwidth IJTAG innovatively leverages the SSN bus architecture, and delivers patterns much faster than traditional serial methods, leading to substantial reduction in test application time, especially for BIST & Mixed Signal IP testing," said Srinivas Vooka, Senior Engineering Manager, Google.

The combination of the features in IJTAG Pro along with the recent announcement of Siemens' Tessent™ AnalogTest software marks a significant expansion of capabilities and bandwidth.

Siemens adds AI to Simcenter Testlab to reinvent modal testing and analysis processes

24 September 2025

Siemens Digital Industries Software announced the latest updates to its Simcenter™ Testlab™ software, including new AI-assisted workflows that accelerate modal analysis processes by up to 7x faster while reducing the personnel needed to perform physical impact testing. Updates also bring automated data capture and processing, improving data quality and consistency across all testing phases - enabling engineers to test faster, smarter and earlier than ever before.

"Siemens consistently delivers on its commitment to leveraging AI to streamline processes and workflows, minimize manual tasks, and accelerate time to market throughout the engineering lifecycle. The latest enhancements in Simcenter Testlab illustrate our approach to integrating AI in order to transform how teams conduct, manage, and interpret physical testing," said Jean-Claude Ercolanelli, Senior Vice President, Simulation and Test Solutions, Siemens Digital Industries Software. "We are leading a significant shift in engineering practices, from design and development through to the essential stages of physical testing."

At the forefront of this test automation revolution is the groundbreaking AI-assisted modal testing capability, which speeds the modal analysis workflow up to 700 percent via enhanced automated mode selection and validation combined with a unified modal analysis dashboard that streamlines the entire modal testing workflow. Furthermore, intelligent sensor placement and automated hit selection simplifies the impact acquisition and reduces the personnel required.

Enhanced Testing and Analysis Tools

- **Transfer Path Analysis (TPA)**: New automation features and processing capabilities in Simcenter Testlab cuts overall analysis time by 40%, making sophisticated NVH predictions more accessible to less experienced users.
- **First ISO 20270-compliant solution:** Cut the time it takes for component characterization from weeks to hours through automated acquisition of blocked forces and impedance FRFs with automated component model extraction solution using Simcenter physical testing hardware and new **Simcenter Testlab Automated Component Model Extractor** software.
- **Streamline test preparation**: Use predefined sequences to automate data processing and validation **in Simcenter Testlab Schedule Designer** to help ensure complete data traceability and virtually eliminate the risk of incomplete or inconsistent test data.

Seamless integration with test hardware

The latest update also seamlessly transfers test plans defined in the Schedule Designer to Simcenter™ SCADAS RS data acquisition system Recorder App. This integration provides clear, wireless tablet-based instructions to operators and enables immediate data validation and processing and thus reduces errors.

In keeping with Siemens' philosophy of openness, Simcenter SCADAS RS now also allows to export data in universal or third-party formats, so the system can work with other software platforms for data processing and analysis.

Siemens and ASE collaborate on Innovator3D IC driven 3Dblox workflows for ASE's VIPack platform

25 September 2025

Siemens Digital Industries Software announced that it is collaborating with Advanced Semiconductor Engineering, Inc. (ASE), the leading global provider of semiconductor manufacturing services in assembly and test, to develop 3Dblox-based workflows for the ASE VIPack™ platform using Siemens' Innovator3D IC™ solution, which is fully certified for the 3Dblox standard..

Siemens and ASE have collaborated to validate 3Dblox workflows for three VIPack technologies, including Fanout Chip-on-Substrate, (FOCoS), Fanout Chip-on-Substrate-Bridge (FOCoS-Bridge), and Through Silicon Via (TSV)-based 2.5D and 3D IC.

ASE's VIPack is comprised of six core packaging technology pillars supported by a comprehensive and integrated co-design ecosystem. As ASE's advanced packaging platform, it is designed to enable vertically integrated package solutions and represents its next generation of 3D heterogeneous integration architecture that extends design rules and achieves ultra-high density and performance. The platform leverages advanced redistribution layer (RDL) processes, embedded integration, and 2.5D and 3D technologies to help customers achieve unprecedented innovation when integrating multiple chips within a single package.

"Siemens' Innovator3D IC provides ASE with a rapid design assembly exploration cockpit that can read and write 3Dblox," said Dr. CP Hung, vice president, Corporate R&D at ASE. "This collaboration allows ASE to optimize efficiency by developing 3Dblox definitions for some of our leading-edge VIPack technologies. It offers our customers EDA tool flexibility to quickly overcome package design challenges and accelerate time-to-market."

3Dblox and Innovator3D IC enable System Technology Co-optimization (STCO) driven hierarchical device planning that is considered mandatory for chiplet-based heterogeneous integration using advanced packaging technologies such as those across ASE's VIPack platform.

"Siemens has had a series of beneficial collaborations with ASE, and we are both committed to 3Dblox for semiconductor package design and verification, as it streamlines the design process and delivers open interoperability," said AJ Incorvaia, senior vice president, Electronic Board Systems, Siemens Digital Industries Software. "As 3Dblox continues to extend we see even greater value and capability that we can deliver to our mutual customers."

Siemens collaborates with TSMC to accelerate 3D IC and AI-driven circuit and systems design

24 September 2025

At the 2025 TSMC North America Open Innovation Platform® (OIP) Ecosystem Forum, Siemens Digital Industries Software announced multiple new collaborations with TSMC, including product certifications and innovative design solutions enablement initiatives for the foundry's newest and most advanced process technologies. Mutual customers can now leverage these advancements, which include substantial innovations in artificial intelligence (AI), 3D IC design, and advanced packaging, to develop compelling and highly differentiated new products.

"Our longstanding relationship with TSMC underscores the transformative power of collaborative innovation," said Mike Ellow, CEO, Siemens EDA, Siemens Digital Industries Software. "By combining Siemens' leading IC and advanced packaging solutions with TSMC's state-of-the-art process technologies, we enable our mutual customers to achieve new levels of design innovation and faster time-to-market, reshaping the future of semiconductor development."

"The collaboration with Siemens illustrates our persistent focus to enable our shared customers for the latest and most advanced process and packaging technologies," said Aveek Sarkar, Director of the Ecosystem and Alliance Management Division at TSMC. "EDA solutions from our OIP partners have significantly contributed to advancing energy-efficient AI chip innovation,

and TSMC will continue working with our ecosystem to enable the rapid proliferation of AI through collaborative efforts."

New collaborations and technology enablement readiness updates include:

AI-focused collaboration with TSMC successfully evaluated Design Rule Check (DRC) productivity improvements using Calibre® Vision AI software. This AI-driven initiative to analyze and prioritize DRC violations demonstrated clear enhancements in debugging efficiency, and the results were jointly validated.

Calibre® nmPlatform software suite is certified for TSMC's advanced processes: Calibre nmDRC, Calibre nmLVS, Calibre PERC™, and Calibre xACT software are all certified for TSMC's advanced N3C, N2P, and A16™ process technologies, enabling mutual customers to continue accessing Siemens' industry-leading signoff technology.

Siemens and TSMC have teamed up to certify Siemens' Solido Simulation Suite software for SPICE accuracy in TSMC's N3C, N2P, and A16 process technologies, enabling customers to create and reliably verify analog, mixed-signal, RF, standard cell, and memory designs using advanced TSMC nodes. This collaboration expands into TSMC's custom design reference flow (CDRF) on its A16 process, as Siemens' Solido Simulation Suite software supports Reliability Aware Simulation technology, which addresses IC aging, real-time self-heating, and Safe Operation Area (SOA) checks. Further, TSMC's CDRF for its A16 process incorporates Siemens' Solido Design Environment software for advanced variation-aware verification, enhancing design sensitivity and automated cell optimization.

Siemens is collaborating with TSMC to certify its Aprisa™ software for TSMC's N2P process. The implementation flow has been validated to meet N2P requirements across placement, routing, chip finishing and engineering change orders (ECOs), with ongoing efforts focused on optimizing performance, power, and area (PPA). This work is aimed at helping customers accelerate design closure and achieve better results on their next-generation designs.

Siemens and TSMC have established major milestones for 3D IC and enabled design flow for TSMC Compact Universal Photonic Engine (TSMC-COUPE™) technology. Siemens' Calibre® 3DSTACK Advanced software is now certified for targeted physical verification solutions while Calibre® 3DThermal software is now certified for static thermal analysis of designs based on TSMC 3DFabric® technologies. Siemens' Calibre 3DThermal software combines the strengths of Calibre technology for detailed chip level analysis, together with the thermal analysis of Siemens' Simcenter™ Flotherm™ software, all of which provide the visibility into thermal impacts throughout the entire design flow and ecosystem. Additionally, Siemens tools have been enabled to support customers to design using TSMC-COUPE™ technology. The companies' joint activity on silicon photonics includes flow development using Siemens' Innovator3D IC™ software, Calibre 3DSTACK software, L-Edit software, Solido Simulation Suite software, Calibre xACT™ software and Calibre Interactive software for design, implementation and verification of TSMC's COUPE technology. Innovator3D IC is enabled for supporting the 3Dblox language format across abstraction levels and Siemens is working to achieve certification for other advanced requirements as 3Dblox continues its transition to become an IEEE standard.

As part of TSMC's cloud-based initiative, Siemens and TSMC have successfully demonstrated Solido Simulation Suite software, Calibre nmDRC software, and Calibre PERC software running in the AWS Cloud. Intended for toolsets qualified under TSMC's N2 Certification, this initiative demonstrates tool accuracy and job parallelism across cloud computing infrastructure, focused on optimizing time to tape-out.

Synopsys Collaborates with TSMC to Drive the Next Wave of AI and Multi-Die Innovation

24 September 2025

Synopsys, Inc. announced its ongoing close collaboration with TSMC to deliver multi-die solutions, encompassing advanced EDA and IP products, that support TSMC's leading-edge processes and packaging technologies, driving innovation in AI chip and multi-die design. The 3DIC Compiler exploration-to-signoff platform and IP, tuned for 3D packaging, along with the company's partnership with TSMC on design enablement has resulted in multiple customer tape-outs.

Building on Synopsys' continued collaboration with TSMC is the availability of certified digital and analog flows, along with the enabled Synopsys.ai™ on TSMC's N2P and A16™ processes using TSMC NanoFlex™ architecture. In addition, Synopsys provides robust automotive IP solutions for TSMC N5A and N3A processes and best-in-class Interface and Foundation IP solutions, delivering highest level of safety, security and reliability while enabling maximum performance with the lowest power for advanced chips.

"Our close collaboration with TSMC continues to empower engineering teams to achieve successful tape outs on the industry's most advanced packaging and process technologies," said Michael Buehler-Garcia, Senior Vice President at Synopsys. "With certified digital and analog EDA flows, 3DIC Compiler platform, and our comprehensive IP portfolio optimized for TSMC's advanced technologies, Synopsys is enabling mutual customers to deliver differentiated multi-die and AI designs with enhanced performance, lower power, and accelerated time to market."

"TSMC has been working closely with our long-standing Open Innovation Platform® (OIP) ecosystem partners like Synopsys to help customers achieve high quality-of-results and faster time-to-market for leading-edge SoC designs," said Aveek Sarkar, Director of the Ecosystem and Alliance Management Division at TSMC. "With the ever-growing need for energy efficient and high-performance AI chips, the OIP ecosystem collaboration is crucial for providing our mutual customers with certified EDA tools, flows and high-quality IP to meet or exceed their design targets."

Synopsys EDA Flows Deliver Enhanced Performance on TSMC Advanced Processes
Synopsys' analog and digital flows, along with the enabled Synopsys.ai, are certified on TSMC N2P and A16™ processes using TSMC NanoFlex™ architecture to help optimize performance, power, and to scale chip designs to advanced semiconductor technologies. Certified capabilities for designs on TSMC A16™ Super Power Rail (SPR) process improve power distribution and system performance, while maintaining thermal robustness of backside routing

designs. Synopsys' pattern-based pin access methodology has been enhanced for TSMC A16™ node to deliver competitive area results. In addition, Synopsys is collaborating with TSMC on the design flow development for TSMC's A14 process and its first process design kit release scheduled for the later part of 2025.

Synopsys IC Validator™ signoff physical verification solution is certified for TSMC A16™ process to support DRC and LVS checking. IC Validator's high-capacity elastic architecture seamlessly scales PERC rules to handle TSMC's N2P full-path electrostatic discharge (ESD) verification with improved turnaround time.

Advanced 3D Stacking and CoWoS Technologies Demonstrate Successful 3D Integration
Synopsys' 3DIC Compiler's unified exploration-to-signoff platform has been enabled to support the TSMC-SoIC® (SoIC-X) technology, including 3D stacked designs and silicon interposer and bridge with CoWoS® technologies, resulting in several customer tape outs. With 3DIC Compiler, customers can achieve higher productivity and faster turnaround times with the platform's automated UCIe and HBM routing, TSV and bump planning, and multi-die signoff verification.

In addition, the ongoing collaboration between Synopsys and TSMC on silicon photonics has enabled an AI-optimized photonic IC flow for TSMC-COUPE™ technology to deliver enhanced system performance and address multi-wavelength and thermal requirements in multi-die and AI designs.

Synopsys Industry-Leading IP Portfolio Paves the Way for Silicon Success
Synopsys is accelerating semiconductor innovation on next-generation TSMC's N2P/N2X processes with the industry's most comprehensive portfolio of best-in-class Foundation and Interface IP. The Synopsys IP portfolio enables the latest high-performance standards, including HBM4, 1.6T Ethernet, UCIe, PCIe 7.0, and UALink, as well as a robust roadmap for automotive, IoT, and HPC applications. Synopsys provides a comprehensive suite of high-performance proven PHYs, embedded memories, high-density logic libraries, programmable IO, and NVM IP. With dedicated IP for N5A and N3A automotive nodes, along with advanced SRAM and Foundation IP for 5nm and 3nm SoCs, Synopsys empowers customers to meet the demanding requirements of next-generation designs across a broad range of markets.

Synopsys Collaborates with TSMC to Enable 2D and 3D Design Solutions

24 September 2025

Synopsys, Inc., announced TSMC has certified the Ansys portfolio of simulation and analysis solutions, enabling accurate final checks on chip designs targeted for TSMC's most advanced manufacturing processes including TSMC N3C, N3P, N2P, and A16™. The companies also collaborated on an AI-assisted design flow for the TSMC-COUPE™ platform. Together, Synopsys and TSMC empower customers to effectively design chips for a range of applications including AI acceleration, high-speed communications, and advanced computing.

Multiphysics and AI-Driven Photonics Design Enablement
Synopsys continues to work with TSMC to expand multiphysics analysis flows for larger designs with hierarchical analysis methodology. The multiphysics flow includes Ansys RedHawk-SC, Ansys RedHawk-SC Electrothermal platform, and Synopsys 3DIC Compiler™ exploration-to-

signoff platform to enable hierarchical thermal-aware timing analysis and voltage-aware timing analysis. This multiphysics approach can help customers accelerate the convergence of large 3DIC designs.

Ansys optiSLang software and Ansys Zemax OpticStudio software transform the design of optical coupling systems in TSMC-COUPE™ architecture by applying AI-assisted optimization along with sensitivity analysis to shorten customer's design cycle times and strengthen design quality. These tools enable engineers to incorporate custom components, such as grating couplers optimized with photonic inverse design using Ansys Lumerical FDTD.

Advanced Process Technology Certifications
Ansys RedHawk-SC and Ansys Totem are foundational solutions for digital/analog power integrity that verify products can function reliably and meet performance goals. The solutions aid in validating power integrity of chips using TSMC N3C, N3P, N2P, and A16™ process technologies. Likewise, Ansys HFSS-IC Pro solution for electromagnetic modeling of chips is certified for TSMC's N5 and N3P processes. In addition, Synopsys is collaborating with TSMC on design flow development for TSMC's A14 process with the first photonic design kit release scheduled for the later part of 2025.

Ansys PathFinder-SC™ is a newly certified electrostatic discharge current density (ESD CD) / Point-to-Point (P2P) checker for the N2P process, validating chip resilience against electrical overstress surges and instilling confidence in engineering teams. Unique in its capacity to quickly check even the largest chips earlier in the design cycle, the solution accelerates the design process and increases product durability. Ansys Pathfinder-SC is enabled to support complex 3D integrated circuit (3DIC) and multi-die systems. Synopsys is working with TSMC to expand the tool capability for large scale 3DIC design analysis.

Ansys HFSS-IC Pro is certified by TSMC for die-level analysis on its advanced 5nm and 3nm process technologies. This collaboration enables customers to meet the demands of complex applications including AI, HPC, 5G/6G communications, and automotive electronics.

"Synopsys provides a broad range of design solutions to help semiconductor and system designers tackle the most advanced and innovative products for AI enablement, data center, telecommunications, and more," said John Lee, vice president and general manager of the semiconductor, electronics, and optics business unit at Synopsys. "Our strong and continuous partnership with TSMC has been a key factor in maintaining our position at the forefront of technology while providing consistent value to our shared customers."

"TSMC's advanced process, photonics, and packaging innovations are accelerating the development of high-speed communication interfaces and multi-die chips that are essential for high-performance, energy-efficient AI systems," said Aveek Sarkar, director of the ecosystem and alliance management division at TSMC. "Our collaboration with OIP ecosystem partners such as Synopsys has delivered an advanced thermal, power and signal integrity analysis flow, along with an AI-driven photonics optimization solution for the next generation of designs."

Tebis presents its revolutionary SmartOps Technology

24 September 2025

Tebis introduces its revolutionary Tebis SmartOps Technology, an innovative solution for automating design and CAM processes, specifically developed to address the requirements of single-part manufacturing. Users benefit from a unique combination of speed, flexibility and process reliability, providing a genuine shortcut to success thanks to consistently reproducible results.

Single-part manufacturing demands rapid, precise solutions—both on the machine and throughout the CAD/CAM process. Tebis SmartOps automates recurring work tasks, significantly reducing the workload on teams. The result: reduced time pressure, increased process reliability, safer manufacturing, and enhanced flexibility for employees.

Working with Tebis SmartOps: Automated, flexible, simple and fast

Tebis SmartOps Technology automates CAD/CAM processes through intuitive, dialog-driven workflows that run nearly autonomously. Users maintain full flexibility to make manual adjustments when needed. Its user-friendly interface speeds up NC programming, while Tebis's end-to-end solutions simplify and automate subsequent production steps.

Modular and scalable: Ideal for all manufacturing needs

SmartOps supports custom configuration: For instance, individual functions can be automated or combined into powerful sets. Typical process steps—such as importing CAD data, measuring blanks, positioning clamping devices, selecting materials and machines, setting measurement points, creating measuring paths, and generating CAM programs—can be linked intelligently and executed efficiently, even by less experienced users. Overall, the complete set of Tebis function modules can be used for SmartOps Technology.

Flexible automation: No scripting or programming language knowledge needed

Tebis SmartOps Technology sets new standards for user-friendliness and flexibility. All tasks are performed within the familiar Tebis environment. Dialogs are fully customizable, with parameters that can be adjusted at any time. Machines, tools, and part variants can be quickly and easily exchanged.

Virtual process libraries: A hub for knowledge management

SmartOps build on the proven Tebis process libraries, which include a comprehensive repository of machines, tools, and manufacturing strategies. This foundation enables the systematic application of a company's manufacturing expertise, ensuring safe, automated, and transparent production processes.

Impactful training: Tech package included

Within just one week, a focused training program equips teams with the skills needed for automated programming of prismatic parts. The featured highlight: A ready-to-use technology package that can be deployed at the company and expanded individually.

Positive feedback from pilot projects: The CAD/CAM process solution—proven in practice

Tebis SmartOps technology, developed in close cooperation with project partners, has already demonstrated its effectiveness across multiple application scenarios. Partners especially

emphasize its user-friendliness and ability to maximize efficiencies in the manufacturing process.

On that subject, Christian Sellerer, Head of Mechanical Manufacturing at Christian Karl Siebenwurst GmbH & Co. KG, has this comment:

Tebis used SmartOps to continuously prepare and program one of our mold manufacturing slides for a milling application. I have to say: This experience makes me eager for more. We see great potential here and expect that SmartOps will help us simplify and improve our CAD and CAM processes. We look forward to learning even more about this new, promising and transformative technology at our workshop with Tebis.

Tech Mahindra Unveils TechM Orion Marketplace, a Global Agentic AI Marketplace to Agentify your Enterprise

23 September 2025

Tech Mahindra, a leading global provider of technology consulting and digital solutions to enterprises across industries, unveiled TechM Orion Marketplace, an Agentic AI marketplace that offers a robust ecosystem of intelligent, autonomous and action-oriented AI agents that collaborate, evolve, adapt, and scale. TechM Orion Marketplace is engineered to centralize AI governance, reduce the cognitive load on employees, and enable AI agents to operate autonomously across complex workflows.

TechM Orion Marketplace leverages advanced Agentic AI frameworks, large language models (LLMs), and machine learning algorithms to provide customized solutions for a wide range of enterprise applications across industries. It empowers agents with faster time-to-value, reduces operational costs, ensures sustained competitive advantage and unlocks measurable business impact. It further ensures intelligent automation is deployed with the right governance while providing scalable AI solutions that continuously learn from process data to accurately predict future scenarios and outcomes.

Birendra Sen, President – Business Process Services, Tech Mahindra, said, *"Most enterprises today are seeking true autonomy where systems can think, act, and adapt. That is exactly what TechM Orion Marketplace delivers. It transforms how organizations view AI from a rule-based engine to an intelligent force capable of driving strategic outcomes. Whether it's small agentic experiments or orchestrating enterprise-wide AI strategies, our Marketplace brings them all under one intelligent, secure, and collaborative ecosystem. It's a step forward to help businesses enter a new era of enterprise autonomy."*

Tech Mahindra launched its TechM Orion platform in July 2025. The introduction of TechM Orion Marketplace marks the next leap forward, showcasing the organization's rapidly evolving suite of agentic AI offerings. TechM Orion Marketplace offers global enterprises AI-powered voice agents and real-time query resolution, enabling agents to make autonomous decisions, adapt, and collaborate in real time. This drives operational excellence, improves productivity, and minimizes errors without constant human intervention.

TJ (Tervinderjit) Singh – Distinguished Analyst – CX – Third Eye Advisor, said*, "TechM Orion Marketplace delivers Agentic AI in an agile, adaptive, scalable, autonomous, and cost-effective mode for clients across vertical/industries looking to transform their business processes. This is Scale at Speed™ - promised and delivered. TechM Orion Marketplace helps augment Agentic AI by offering agile, adaptive, high quality, scalable, autonomous and cost-effective solutions for enterprises across vertical/industries that want to transform their business processes, reduce complexity and improve competitive advantage."*

The development of TechM Orion Marketplace is a strategic extension of Tech Mahindra's focus on platform-led, AI-first solutions. It aligns closely with Tech Mahindra's "AI Delivered Right" philosophy, prioritizing enterprise-grade AI that is ethical, responsible, and results-oriented. With this Marketplace, Tech Mahindra strengthens its commitment to helping enterprises stay ahead in a rapidly evolving digital economy.

TOPSOLID to release GPU based simulation using MachineWorks

22 September 2025

TOPSOLID SAS will enhance the productivity of TopSolid CAM by including MachineWorks GPU.

MachineWorks Ltd is pleased to announce that TOPSOLID SAS, a leading supplier of advanced CAD, CAM, PDM and ERP solutions, will enhance the productivity of TopSolid CAM by including the recently released MachineWorks GPU.

By exploiting the high level of parallelism available in modern GPUs, MachineWorks GPU is able to create an accurate in-process stock model in seconds, rather than in minutes or hours. Such a major performance improvement is expected to very significantly improve the efficiency, and hence productivity, of a wide variety of CAM workflows.

Patrice Tiberi, Deputy CEO, Director of Product Strategy and Development at TOPSOLID, said "We are of course impressed by the huge boost in performance offered by performing CNC simulations on the GPU. We expect this will open many doors for us over time and look forward to working closely with MachineWorks to drive forward this important productivity aid. We were also pleased to find that integrating the new tool was very easy – it uses the same API calls as their other stock modelling engines, so we were able to drop it in and start testing with minimal effort."

Dr Fenqiang Lin, Managing Director of MachineWorks, commented, "We are very impressed how quickly the TOPSOLID team have moved forward with their integration and testing. TOPSOLID has been a close and important partner for MachineWorks for over twenty years now, and we're pleased to be able to support them in contributing to a new era of manufacturing productivity."

GPU features will be available in the next major release of TopSolid, TopSolid 2026 (v7.20) RTM, planned for January 2026.